

Microfluidics

the science and technology for
miniaturized laboratories on-chip

vania.silverio@tecnico.ulisboa.pt



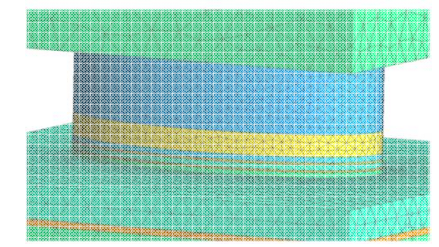
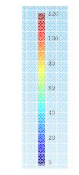
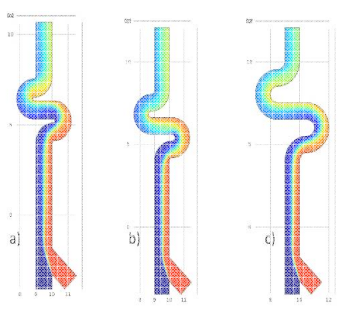
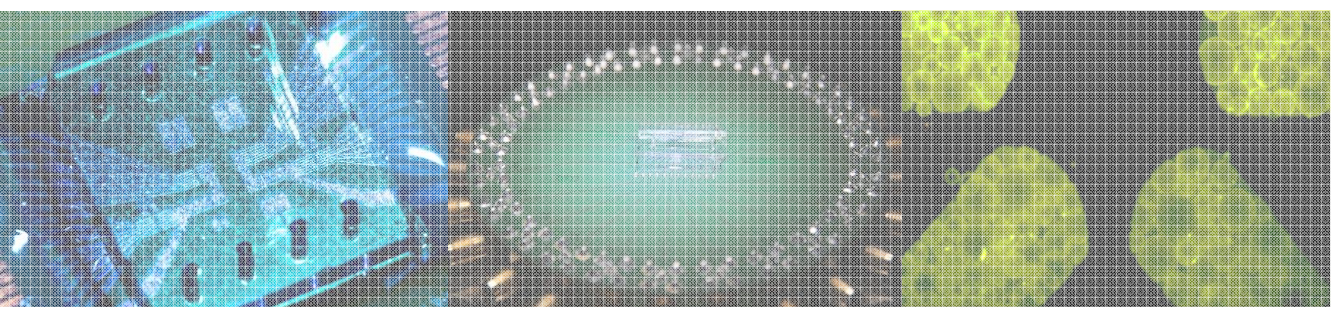
- SPINTRONICS AND BIOSENSORS
- MEMS AND BIOMEMS
- MAGNETIC NANOSTRUCTURES AND NANODEVICES
- BIOANALYTICAL ENGINEERING
- WIDE BANDGAP SEMICONDUCTORS
- MATERIALS SIMULATIONS

Training, service providing, protocols for regular user access

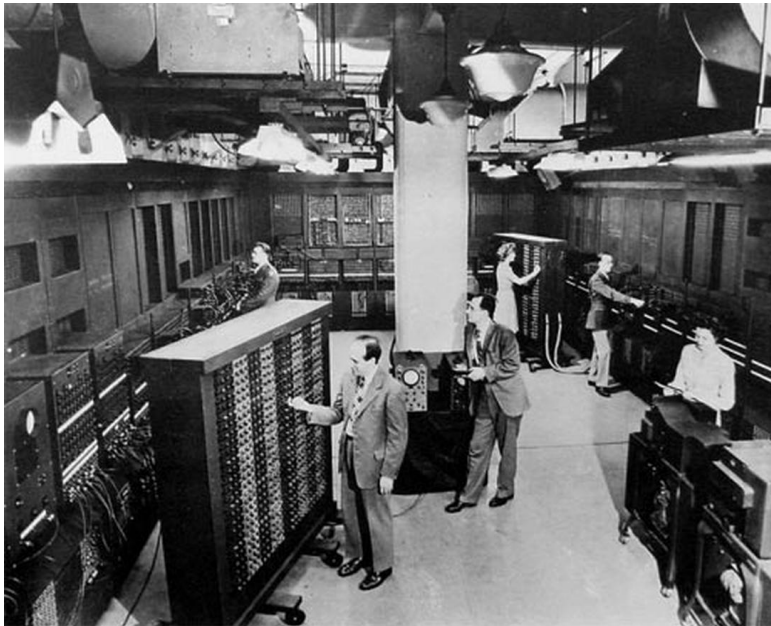


18th International Flow Measurement Conference

Portugal | Lisbon | LNEC | 26-28 June 2019



MINIATURIZATION

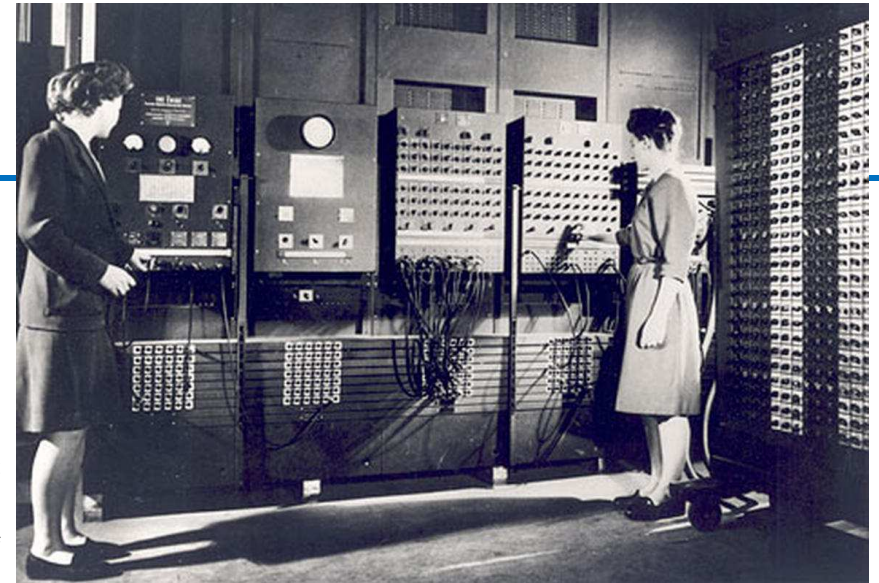


Fine-tuning ENIAC

J. Presper Eckert (the man in the foreground turning a knob) served and John Mauchly (center) designed ENIAC to calculate the trajectory of artillery shells. The machine didn't debut until February 1946, after the end of World War II, but it did launch the computer revolution.

trajectory exam

Frances Blias and Elizabeth Jennings with ENIAC. Women performed many of the mathematical calculations and developed the programming techniques. Although they didn't get credit at the time, their role has recently become better acknowledged. "The audience was absolutely astounded. ENIAC ran the trajectory faster than it took the bullet to trace it. People got, as a souvenir, a printout of the trajectory we ran," said Jean Bartik, one of the surviving programmers, about the first demonstration of ENIAC to the military and other scientists.



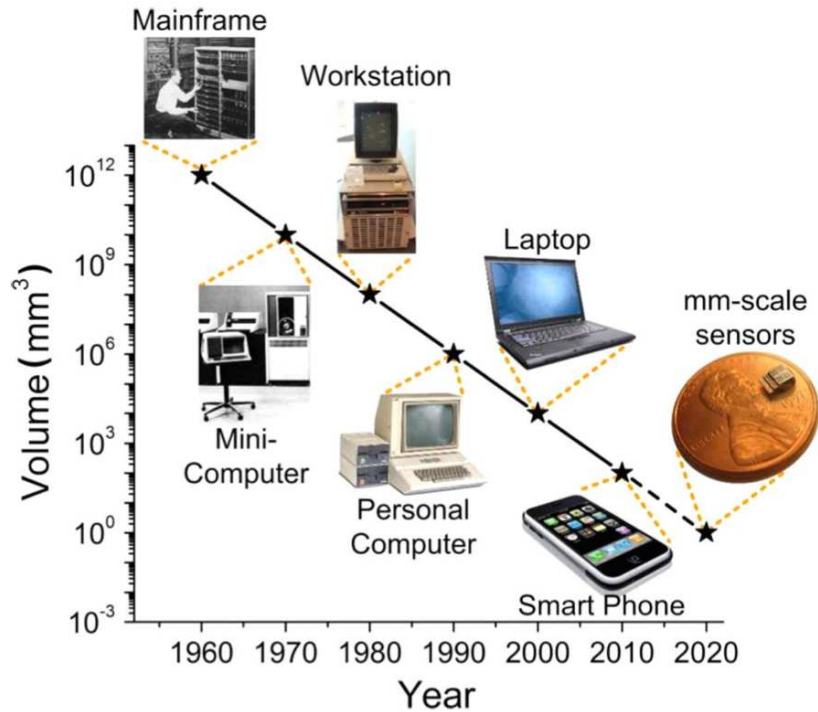
Eckert-Mauchly Computer

Mauchly and one of ENIAC's programmers. After a disagreement with the University of Pennsylvania over patents, Mauchly and Eckert left to form the Eckert-Mauchly Computer, which was bought a few years later by Sperry Rand and later became Unisys. Although Eckert stayed on, Mauchly left and was nearly broke when he died in 1980.



The World's Smallest Computer

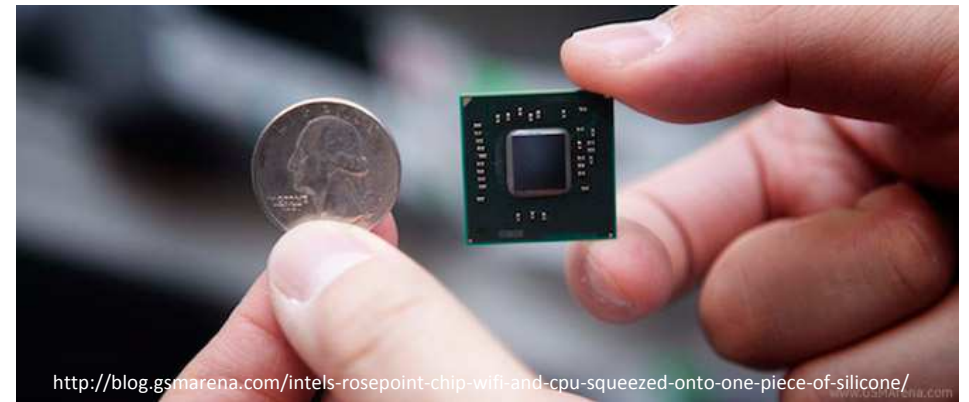
Dag Spicer March 26, 2015 Curatorial Insight, From the Collection



<http://www.computerhistory.org/atcm/the-worlds-smallest-computer/>

Intel's Rosepoint chip: WiFi and CPU squeezed onto one piece of silicone

February 21st, 2012, 04:19 by Alex



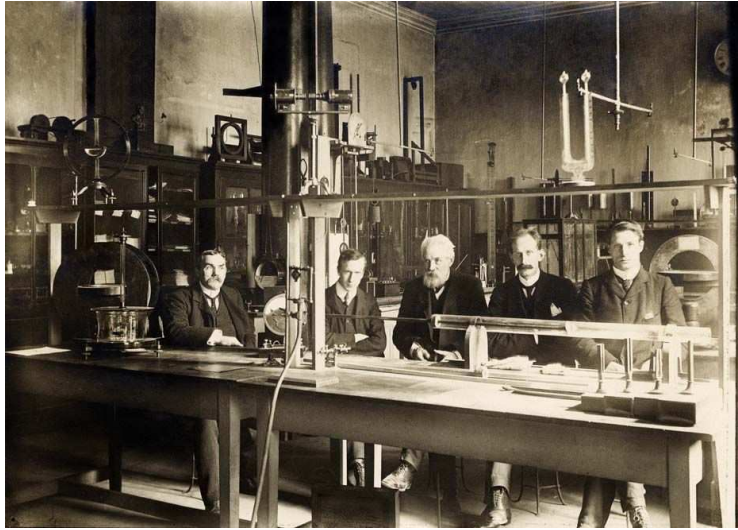
<http://blog.gsmarena.com/intels-rosepoint-chip-wifi-and-cpu-squeezed-onto-one-piece-of-silicone/>

ZOTAC Reveals Next-Gen Pico Mini PCs With Latest CPUs From Intel And AMD

by Microsoft News @msftnws
Jan 10, 2015 at 1:47 GMT



<https://mpoweruser.com/zotac-reveals-next-gen-pico-mini-pcs-with-latest-cpu-from-intel-and-amd/>

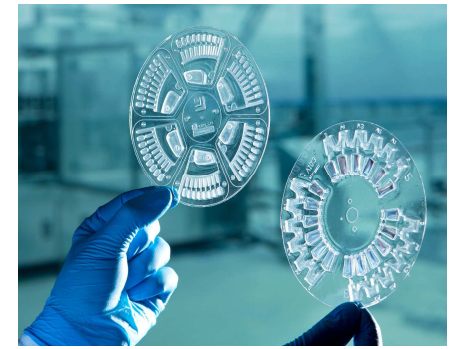
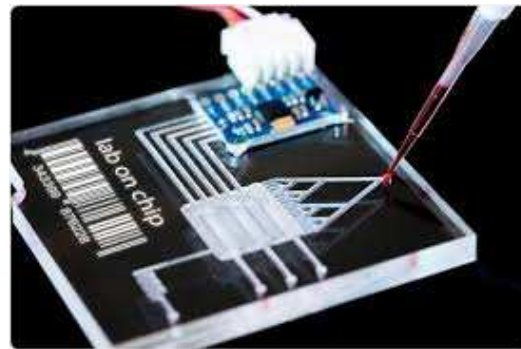


CHEMICAL LABORATORY IN THE 30'S

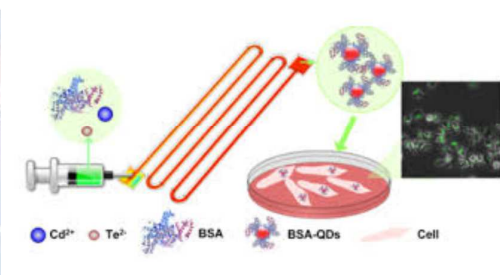
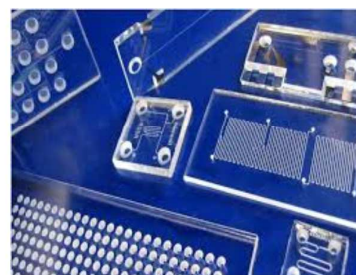
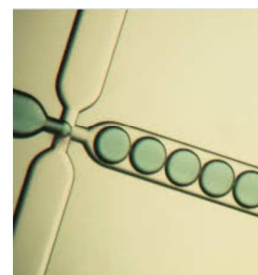
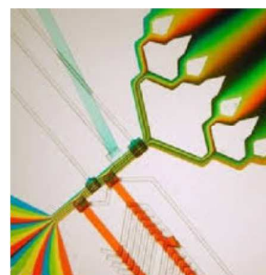
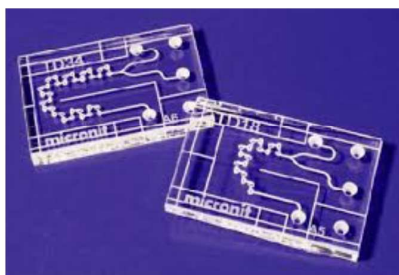
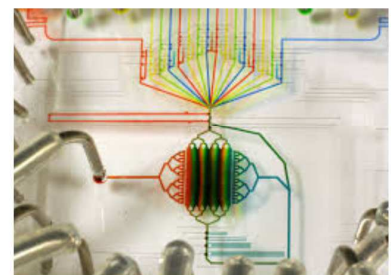
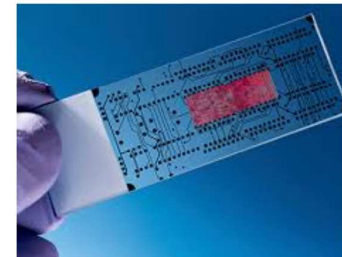
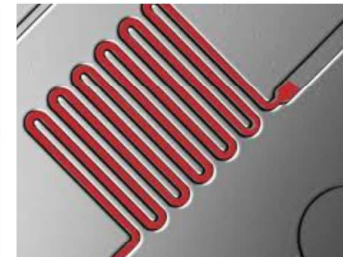
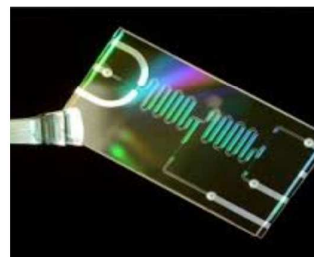
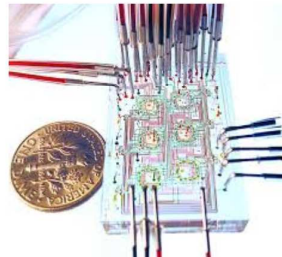
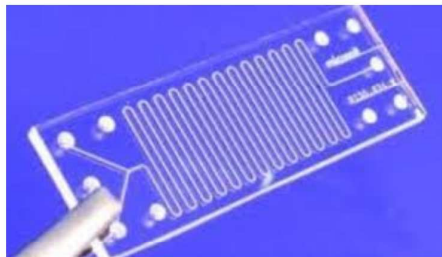
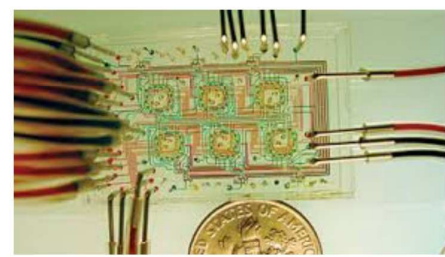
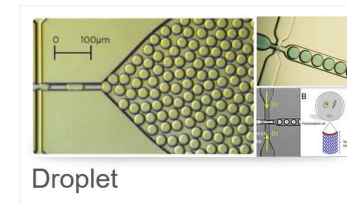
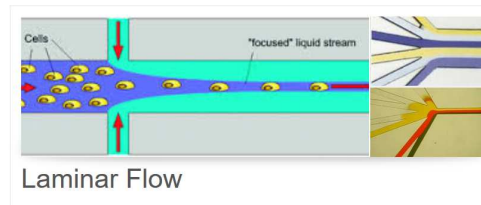
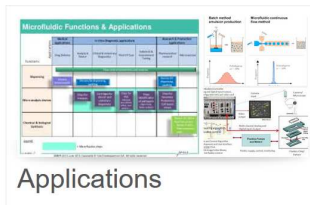
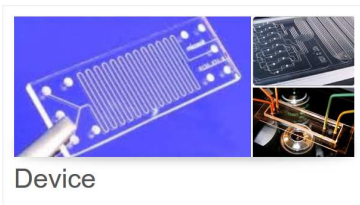
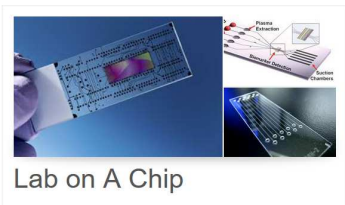


LIFE SCIENCES LABORATORY IN ~ 2000

**LABORATORIES
OF THE FUTURE**



MICROFLUIDICS



MINIATURIZATION

mi · cro · flu · id · ics (*mī'krō flōō id'iks*)

“It is the science and technology of systems that process or manipulate small amounts of fluids, using channels with dimensions of tens to hundreds of micrometres.”

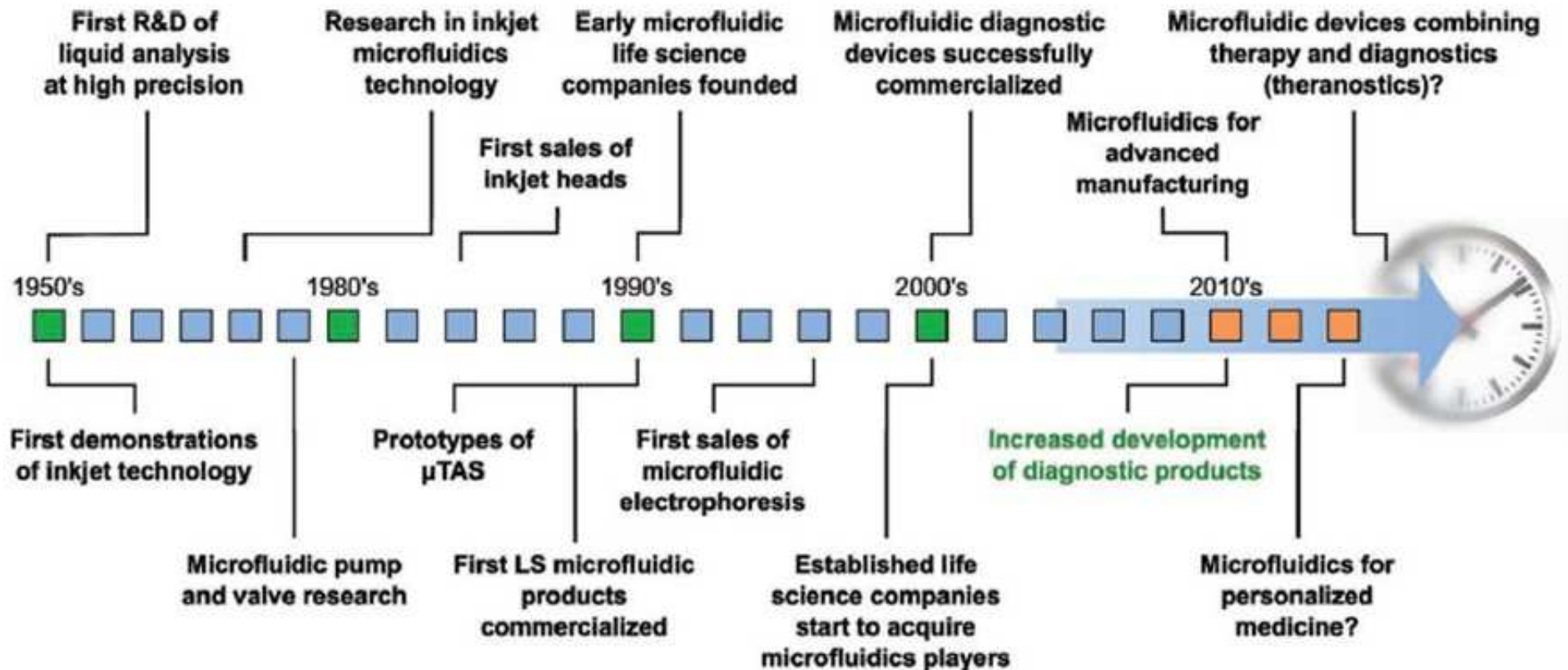
GM Whitesides, The origins and the future of microfluidics, Nature 442(2006)368-373

dominated by

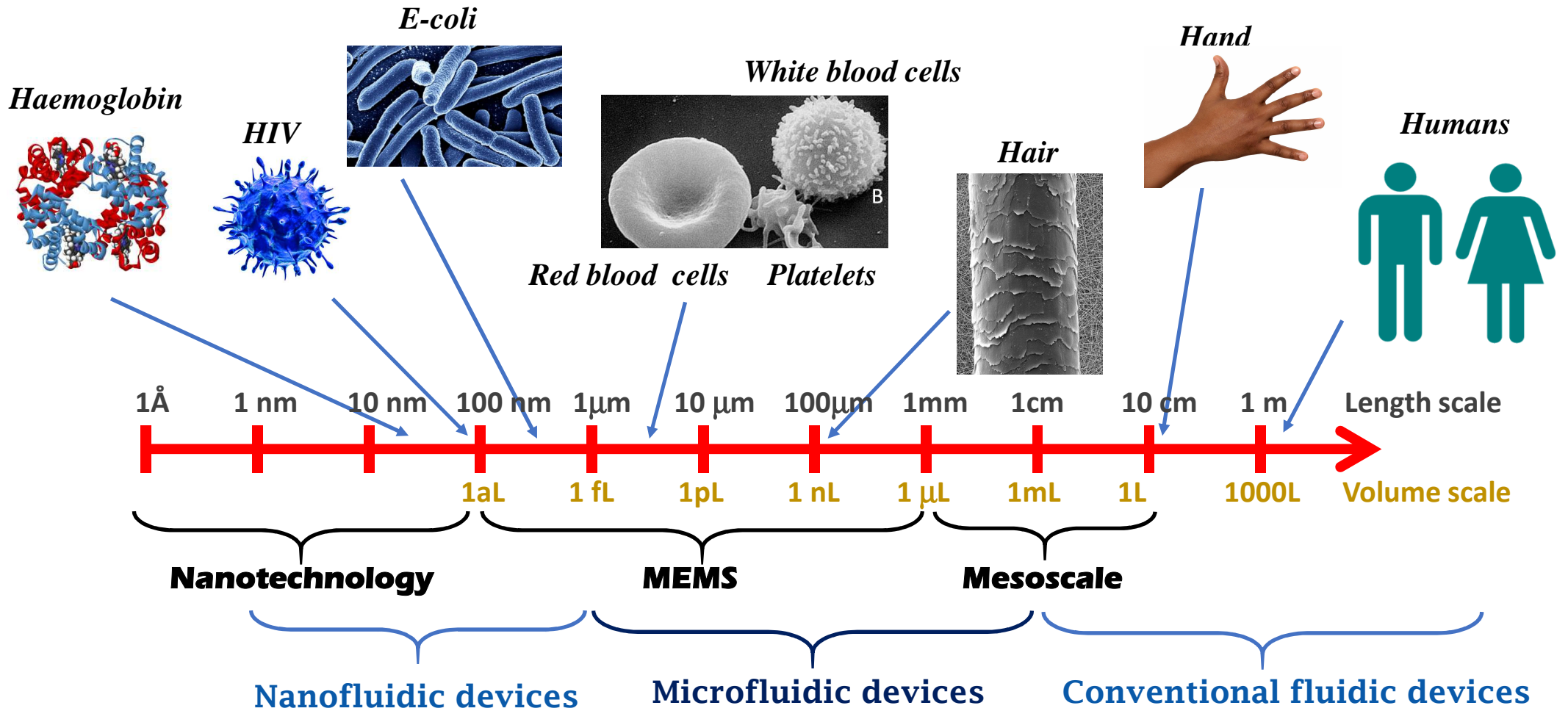
Surface tension
Energy dissipation
Fluidic resistance



EVOLUTION OF MICROFLUIDICS TECHNOLOGY



LENGTH SCALES



WHY MICROFLUIDICS ?

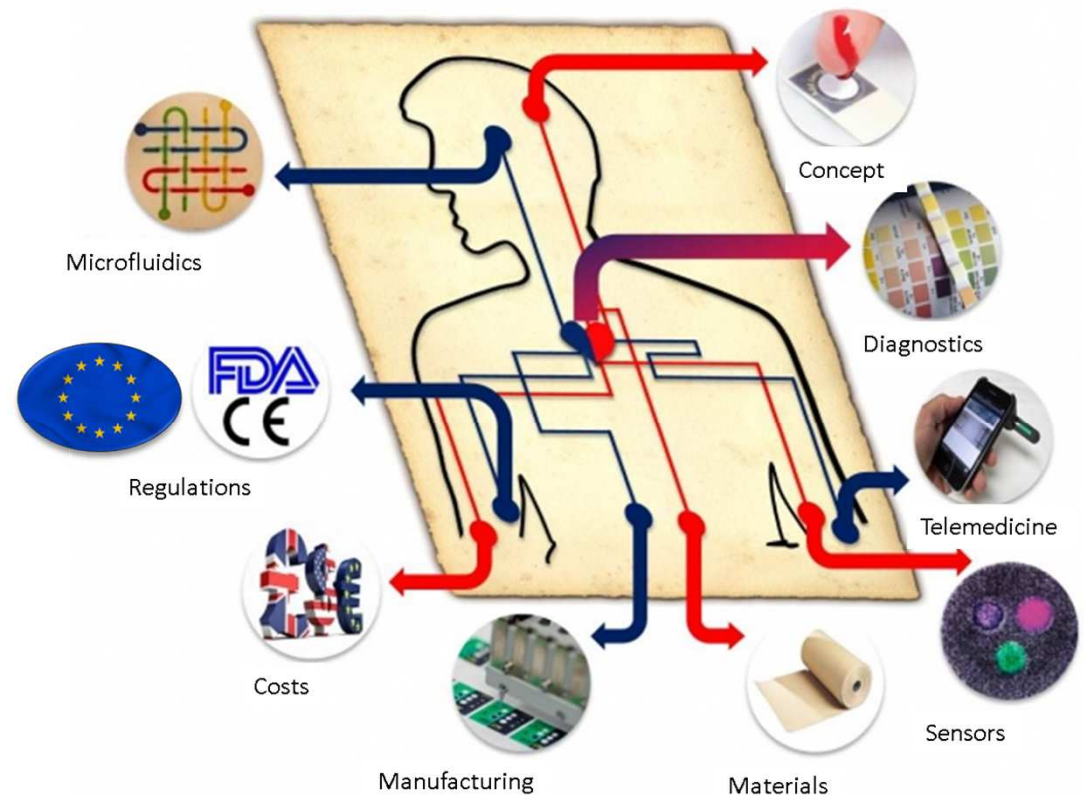
- Required when the application demands handling of **very small liquid volumes** (ex: inkjet printers, drug administration, chemical microanalytical systems, ...)

- **Advantages of scaling down**

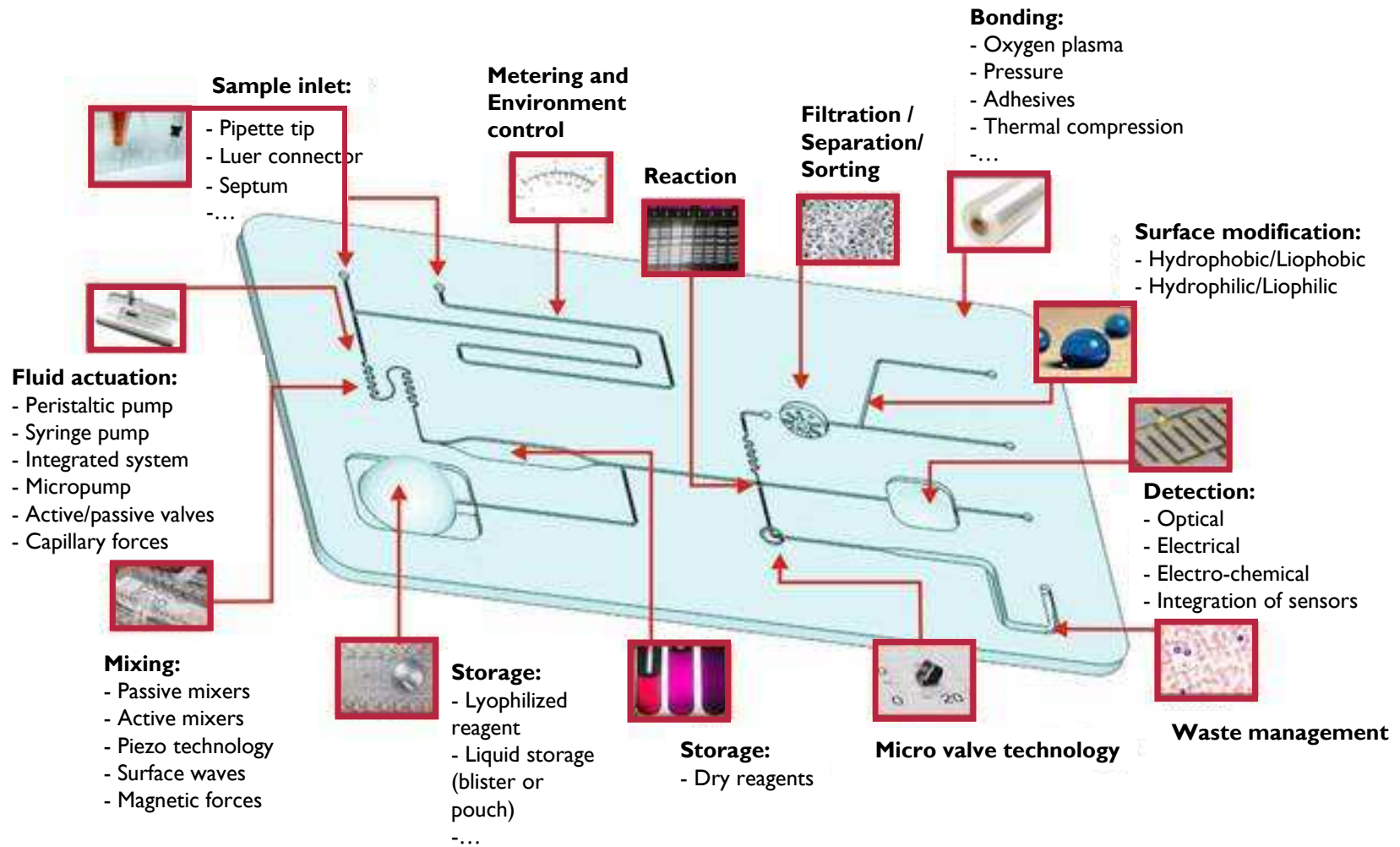
- **Decreased** sample and reagent volumes
- **Faster** response : shorter diffusion distances
- Paralell, multitarget and **multiplex** detection
- **Portable**
- **Small economic footprint**
- Efficient **automation** and **integration**: several functions at the same chip – lab-on-a-chip, μ TAS, organ-on-chip, lab-on-a-CD, ...

- **Disadvantages of scaling down**

- Increased surface tension influence

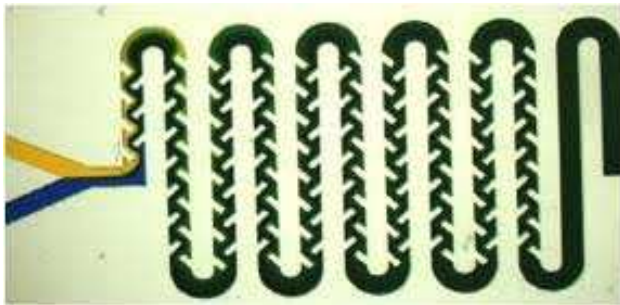


MICROFLUIDICS INTEGRATION

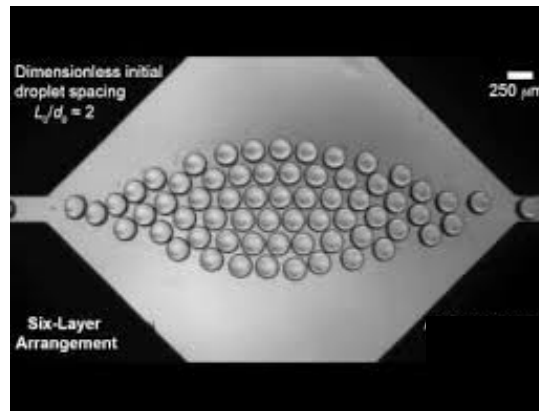


MICROFLUIDICS FEATURES

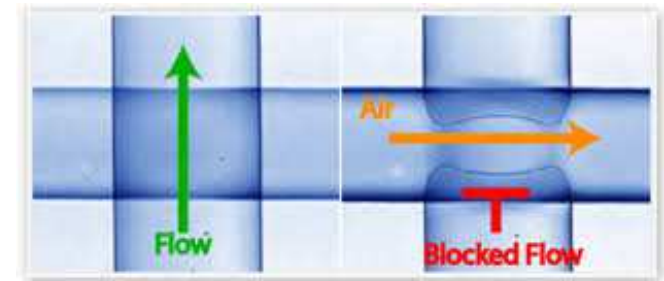
Mixers



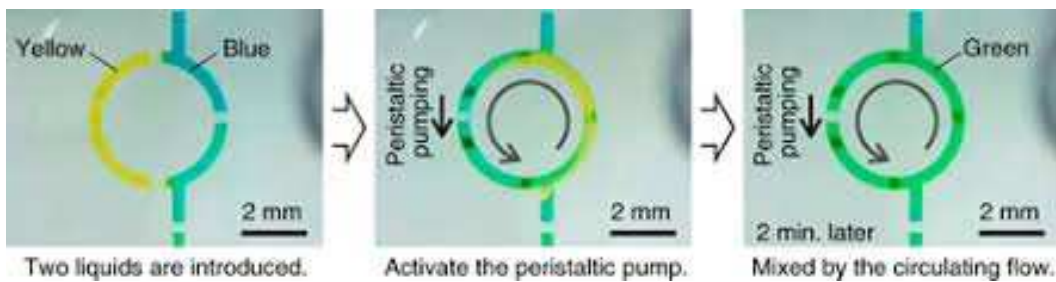
Chambers



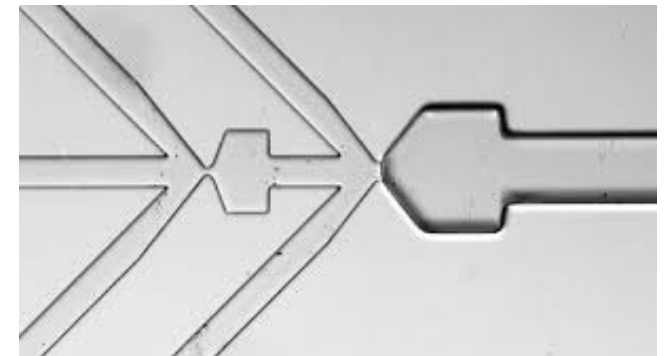
Valves



Pumps

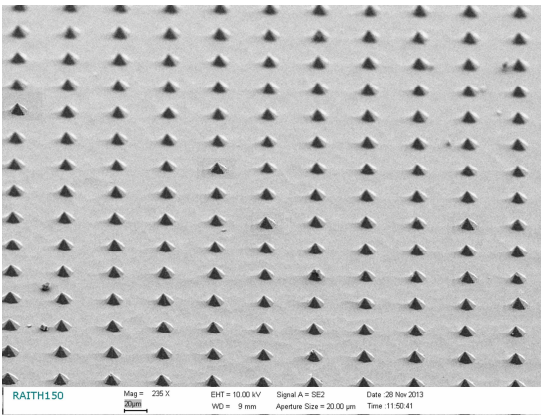


Nozzles

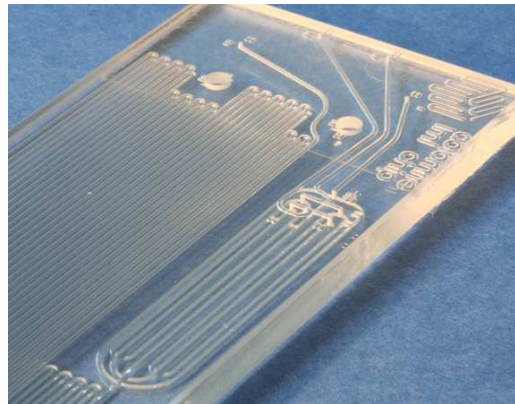


MICROFLUIDICS FEATURES

Needles



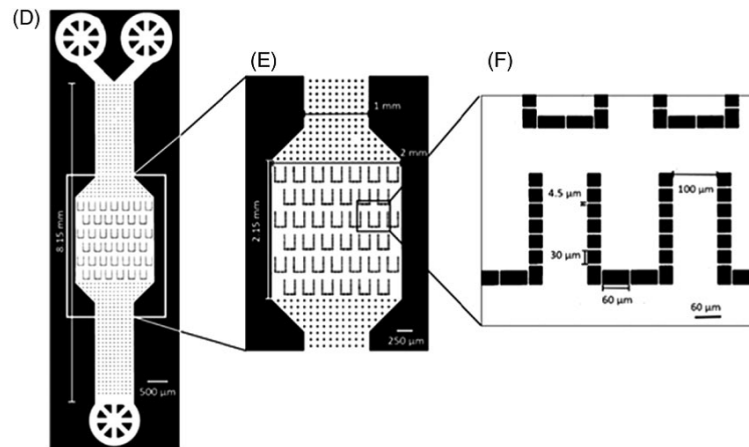
Reactors



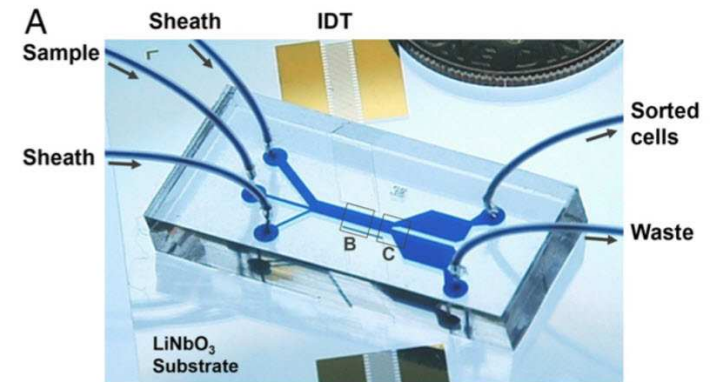
Dispensers



Filters

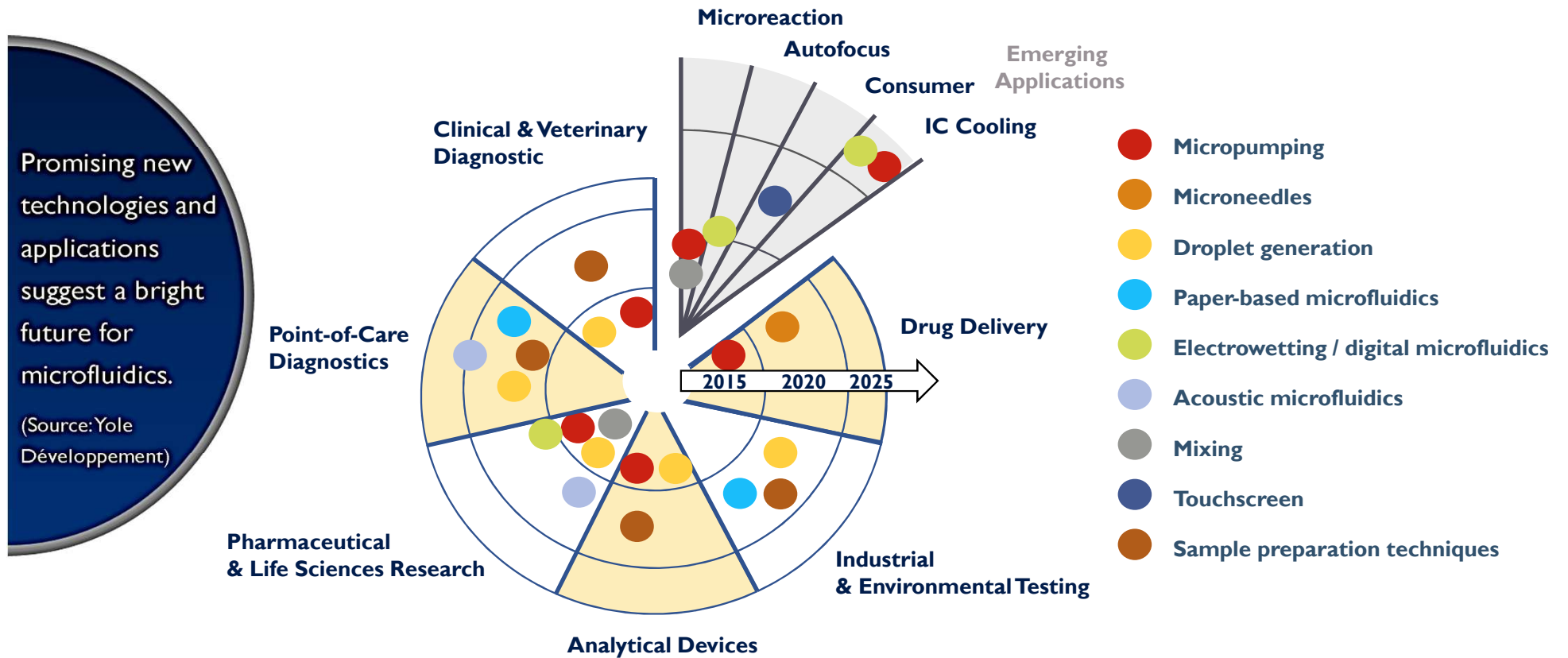


Separators



MICROFLUIDIC TECHNOLOGY/APPLICATIONS ROADMAP

(Source: *Microfluidic Applications in the Pharmaceutical, Life Sciences, In-Vitro Diagnostic, and Medical Device Markets* report, Yole Développement, June 2015)

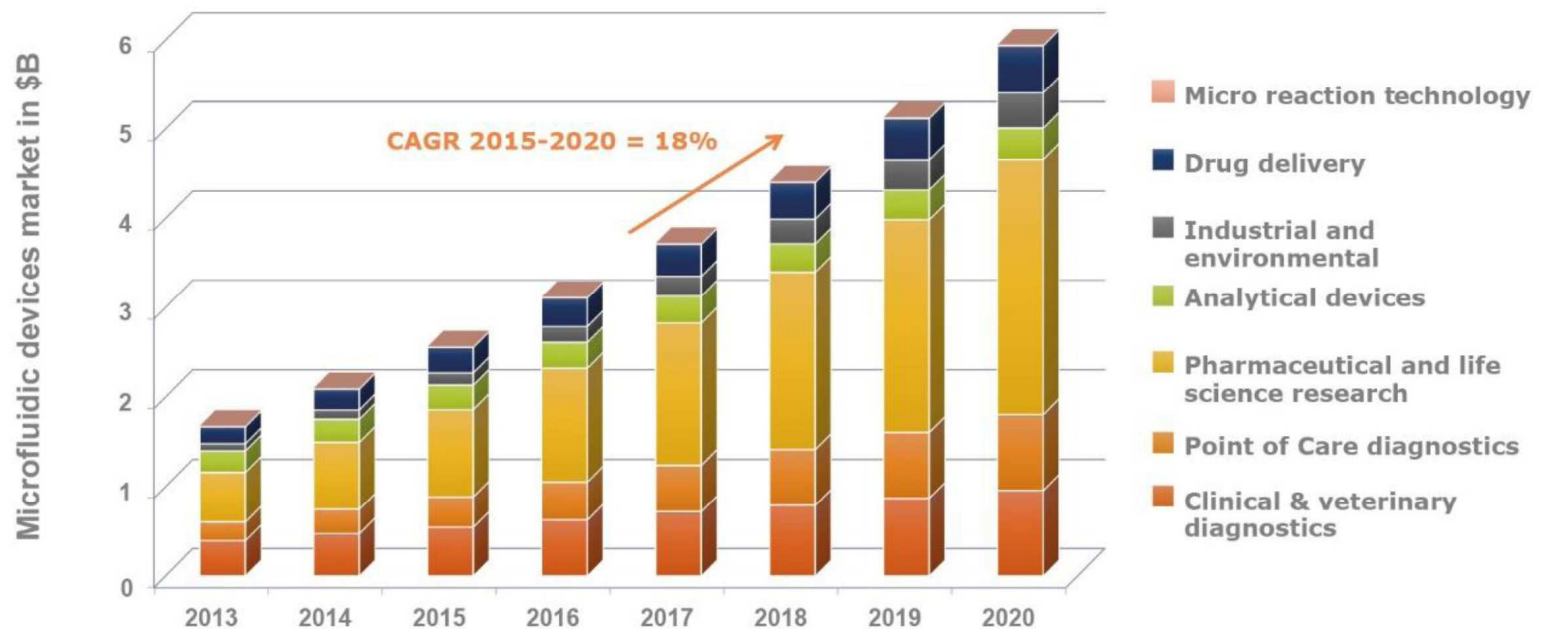


MICROFLUIDIC DEVICES MARKET IN \$B

(Source: Microfluidic Applications in the Pharmaceutical, Life Sciences, In-Vitro Diagnostic, and Medical Device Markets report, Yole Développement, June 2015)

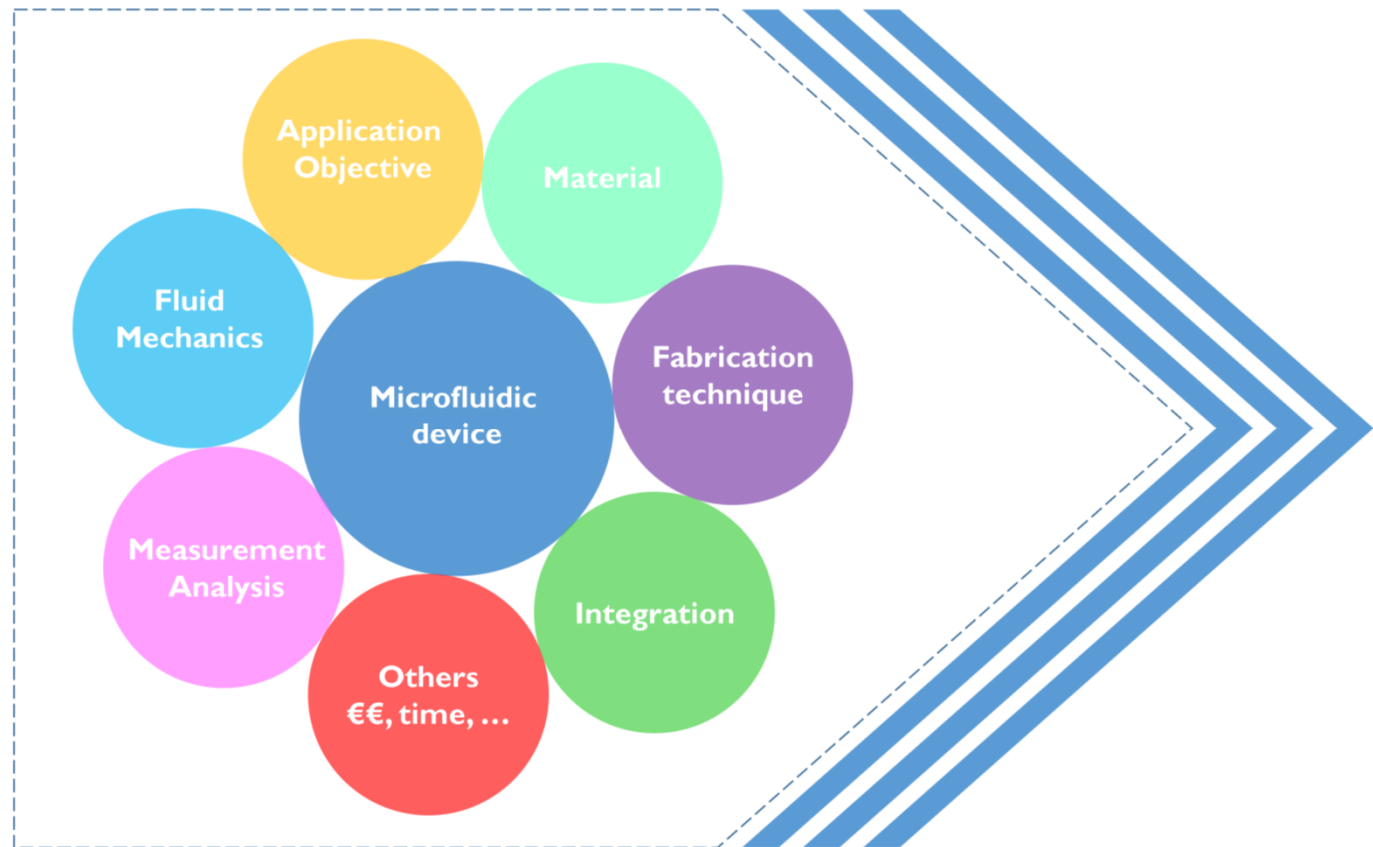
The microfluidic industry is now well structured for further growth.

(Source: Yole Développement)



https://www.slideshare.net/Yole_Developpement/microfluidic-applications-reportjune2015sample

HOW TO START ?

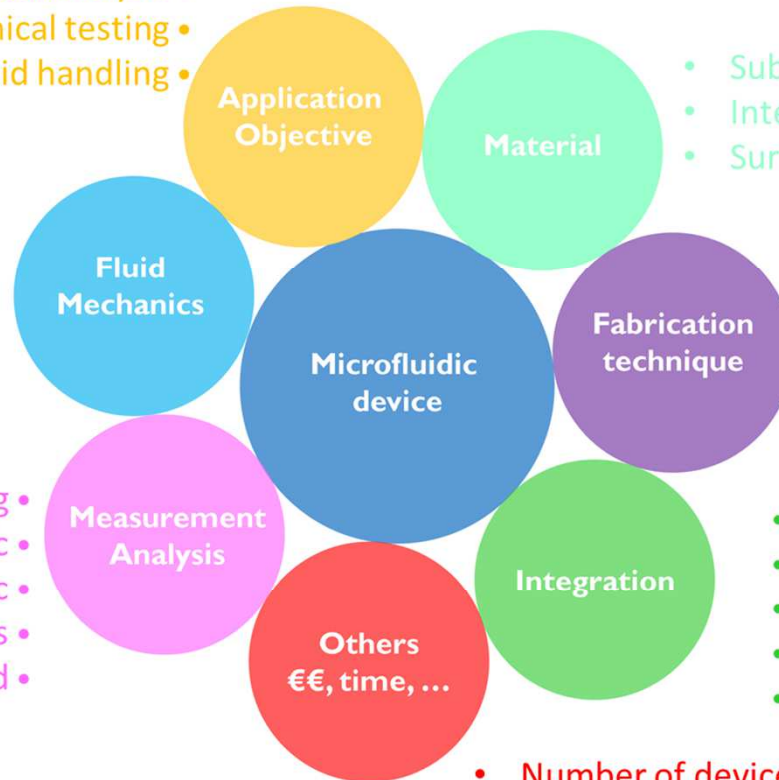


HOW TO START ?

- Bio/medical, chemical, physical analysis
- POC testing, Drug delivery, clinical testing
- Microreactors, flow control, fluid handling

- Navier Stokes
- Simplifications possible
- Newtonian / non-Newtonian
- Dimensions
- Flow conditions, v, T, p, τ, \dots
- CFD

- Internal / external sensing
- Optical, chemical, thermal, magnetic
- electrochemical, NMR, acoustic, etc
- Integrated electronics
- Computer controlled



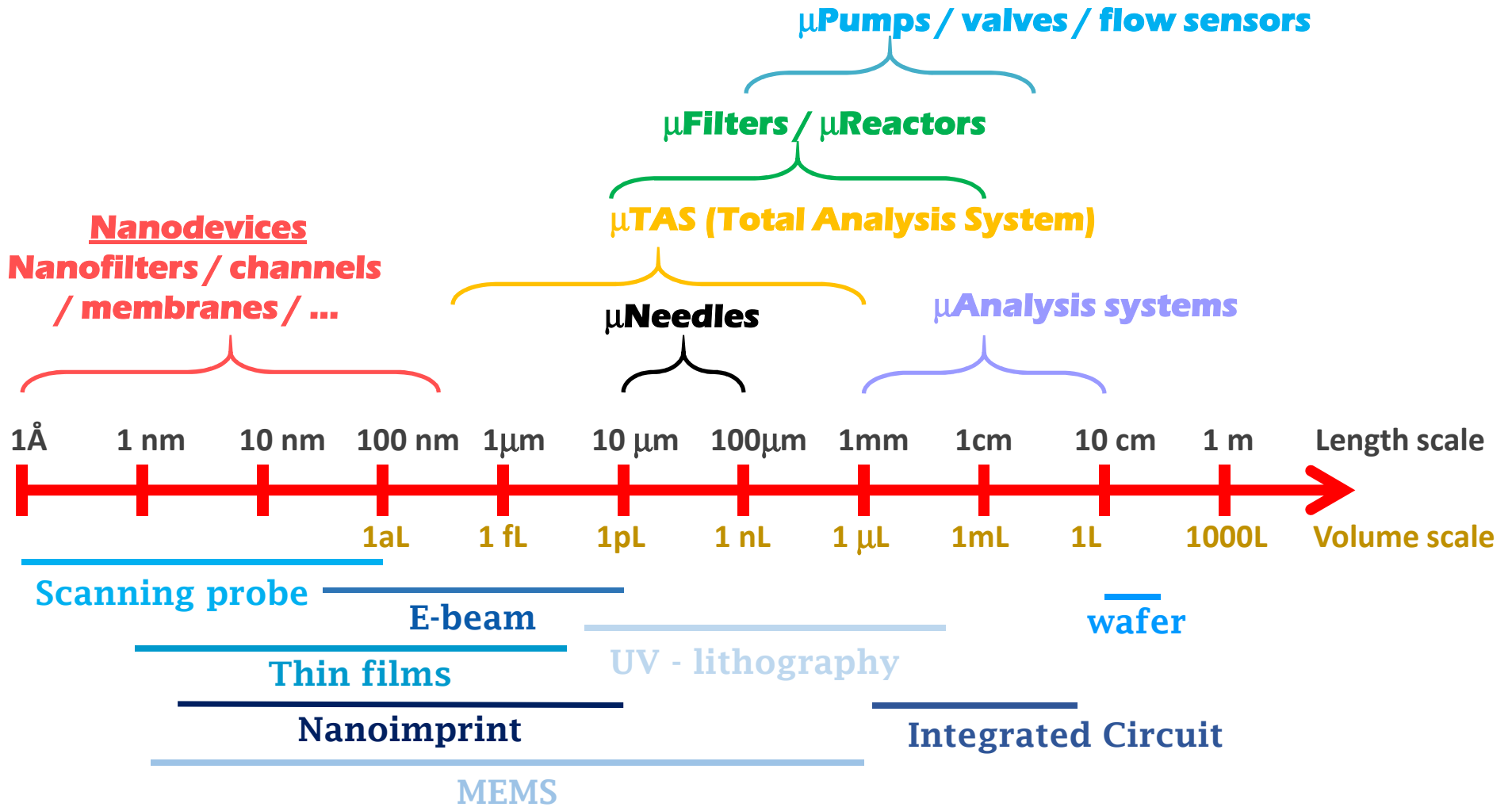
- Substrate properties
- Interaction fluid/surface
- Surface modification

- Clean room microfabrication
- Soft lithography
- Thermal molding
- Bonding

- Sensors
- Actuators
- Valves
- Pumps
- Connecting to the world

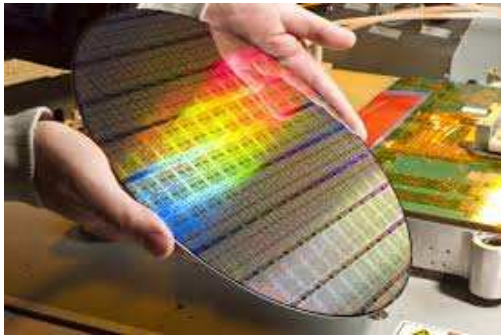
- Number of devices
- Existing expertise
- Going to market

LENGTH SCALES

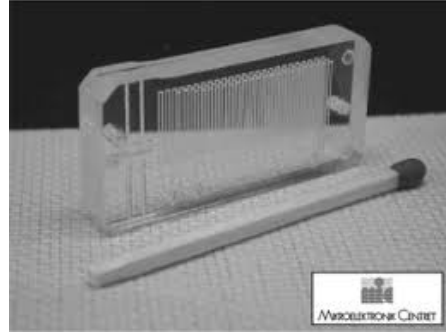


MICROFABRICATION MATERIALS

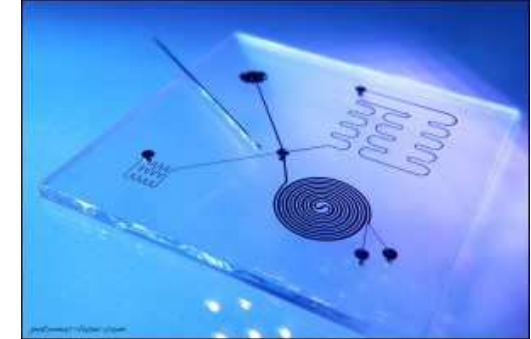
Silicon



Glass, Quartz



Thermoplastics: PMMA, PC, PEEK, COC, COP, PS



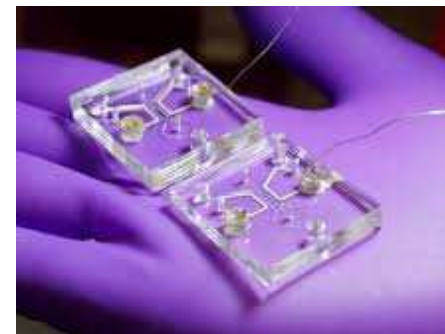
Ceramics



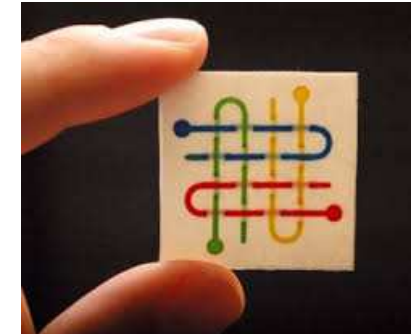
Metals



Elastomers: PDMS



Paper



KEY FABRICATION TECHNOLOGIES

Si / Glass

Lithography

Wet etching

Dry etching

Thin film deposition

Wafer bonding

Elastomer

Hardmask

Coating

Soft lithography

Elastomer casting

Bonding

Polymer

Hot embossing

Micromilling

IM and HE mold (insert)

Injection moulding

Bonding

General / back-end

Electrical, analytical
and/or fluid Interfacing

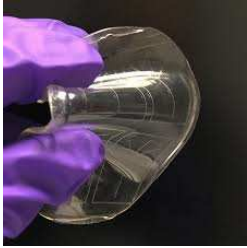
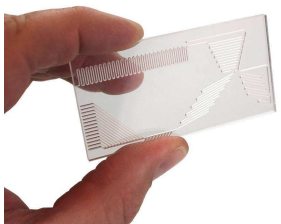
Coating

Hybrid assembly

Flip-chip bonding

Dicing/packageing

MICROFABRICATION TECHNIQUES



QUICK

Injection Molding and Hot Embossing

- + : High-throughput
- : Cost, Features, Equipment

Mold
Plastic
Heater / Cooler

Replica Molding

- + : Easy, Time, Cost
- : Deformable, Pressure

Polymer
SU-8 wafer

EXPENSIVE

CHEAP

Silicon and Glass Machining

- + : Features, Pressure
- : Cost, Time, Equipment

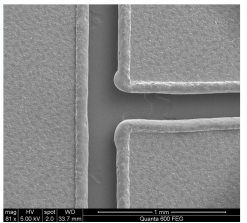
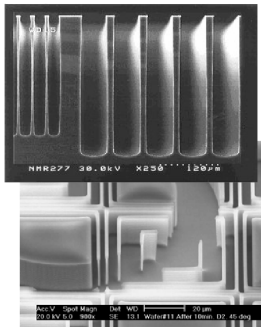
Glass / silicon
Silicon

Polimer Machining and Laser Ablation

- + : Integration, Cost
- : Time, Features, Pressure

Plastic

SLOW



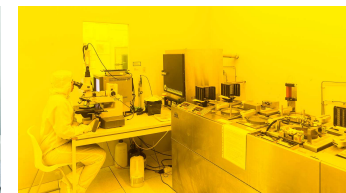
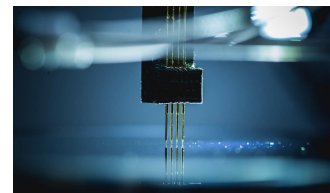
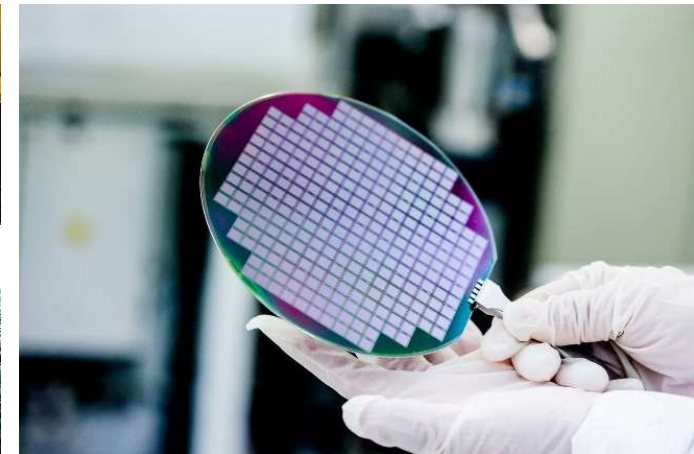
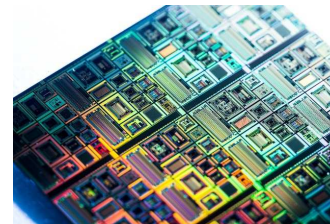
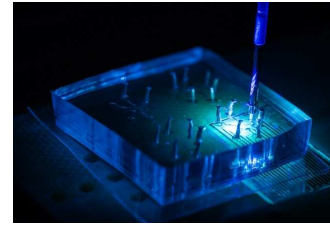
(a)

INESC-MN INFRASTRUCTURES

- Cleanroom Class 10/100 (~100m²)

ISO Class	Fed Std 209E Class	Maximum Number of Particles in Air (Particles per cubic meter)					
		≥ 0.1 μm	≥ 0.2 μm	≥ 0.3 μm	≥ 0.5 μm	≥ 1 μm	≥ 5 μm
ISO 1		10	2				
ISO 2		100	24	10	4		
ISO 3 (Class 1)		1,000	237	102	35	8	
ISO 4 (Class 10)		10,000	2,370	1,020	352	83	
ISO 5 (Class 100)		100,000	23,700	10,200	3,520	832	293
ISO 6 (Class 1,000)		1,000,000	237,000	102,000	35,200	8,320	2,930
ISO 7 (Class 10,000)					352,000	83,200	2,930
ISO 8 (Class 100,000)					3,520,000	832,000	29,300

- Silicon backened processing for feature sizes down to **20 nm**
- Up to **8 inch wafer (200 mm)** processing
- Area for support equipment and film deposition cleanroom Class 10000 (~150m²)
- Chemical wetbench for biological processing
- Laboratories for film and device characterization



INESC-MN INFRASTRUCTURES

➤ Cleanroom C (~100m²)

➤ Silicon backe to **20 nm**

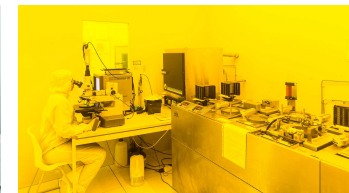
➤ Up to **8 inch**

➤ Area for sup cleanroom C

➤ Chemical we

➤ Laboratories

		Maximum Number of Particles in Air (Particles per cubic meter)					
ISO Class	Fed-Std 209E Class	Particle Size					
		≥ 0.1µm	≥ 0.2µm	≥ 0.3µm	≥ 0.5 µm	≥ 1µm	≥ 5 µm
ISO 1		10	2				
ISO 2		100	24	10	4		
ISO 3	(Class 1)	1,000	237	102	35	8	
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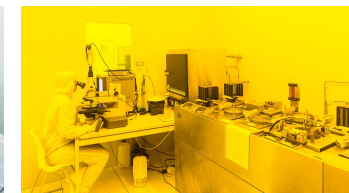
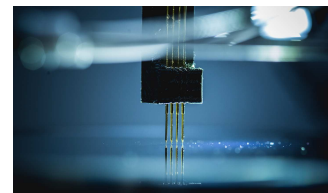
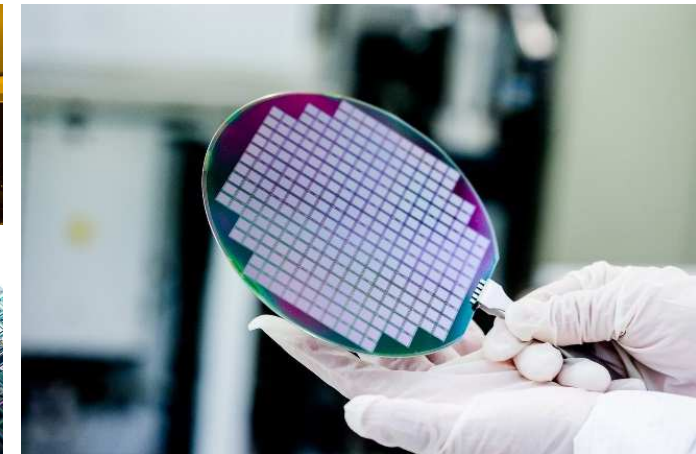
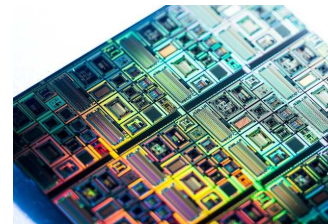
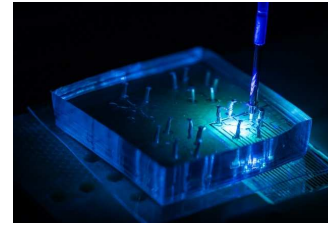


INESC-MN INFRASTRUCTURES

- Cleanroom Class 10/100 (~100m²)

ISO Class	Fed Std 209E Class	Maximum Number of Particles in Air (Particles per cubic meter)					
		≥ 0.1 μm	≥ 0.2 μm	≥ 0.3 μm	≥ 0.5 μm	≥ 1 μm	≥ 5 μm
ISO 1		10	2				
ISO 2		100	24	10	4		
ISO 3 (Class 1)		1,000	237	102	35	8	
ISO 4 (Class 10)		10,000	2,370	1,020	352	83	
ISO 5 (Class 100)		100,000	23,700	10,200	3,520	832	293
ISO 6 (Class 1,000)		1,000,000	237,000	102,000	35,200	8,320	2,930
ISO 7 (Class 10,000)					352,000	83,200	2,930
ISO 8 (Class 100,000)					3,520,000	832,000	29,300

- Silicon backened processing for feature sizes down to **20 nm**
- Up to **8 inch wafer (200 mm)** processing
- Area for support equipment and film deposition cleanroom Class 10000 (~150m²)
- Chemical wetbench for biological processing
- Laboratories for film and device characterization



INESC-MN INFRASTRUCTURES

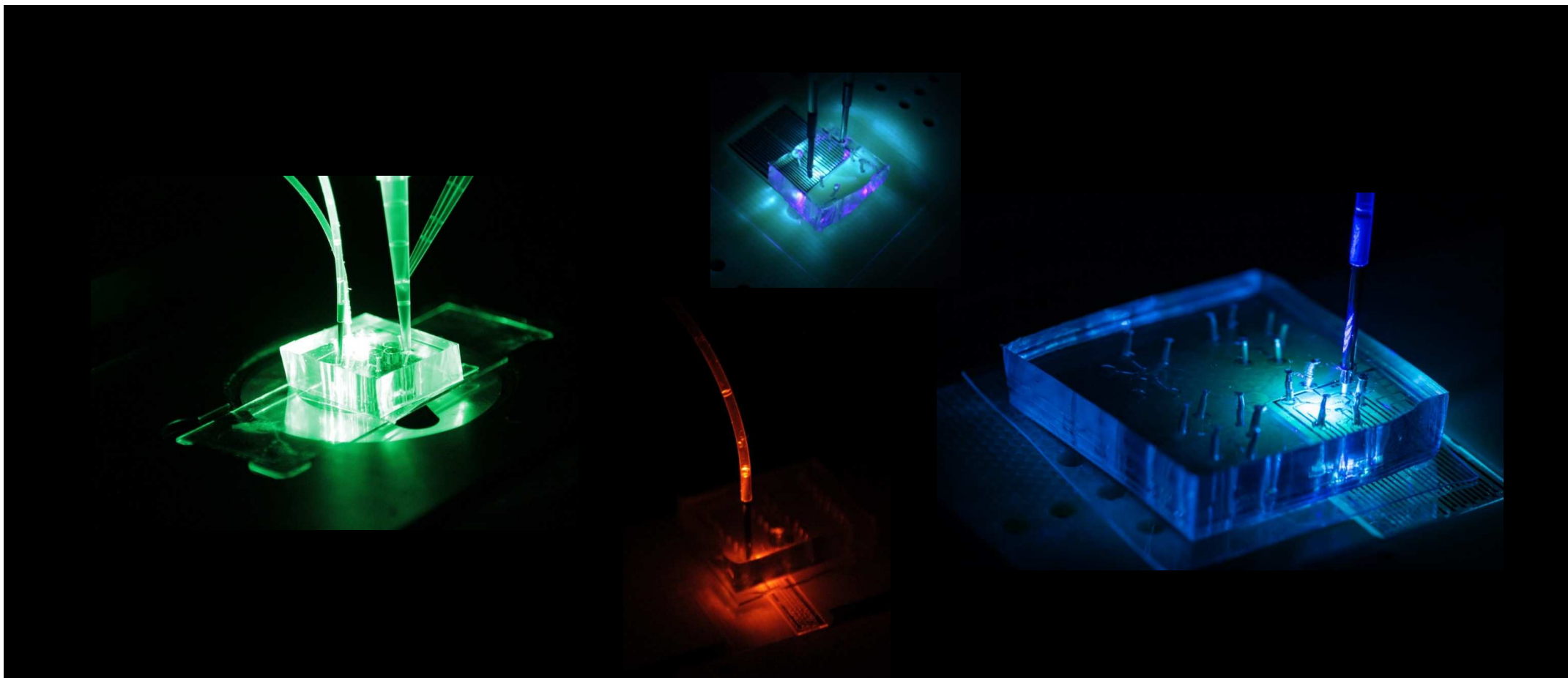
- Controlled temperature (20°C), air pressure, humidity, airborne particles, vibration, lighting, etc.



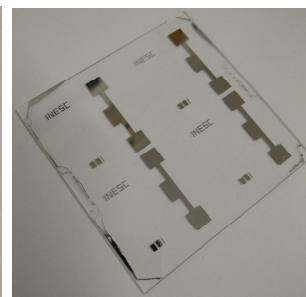
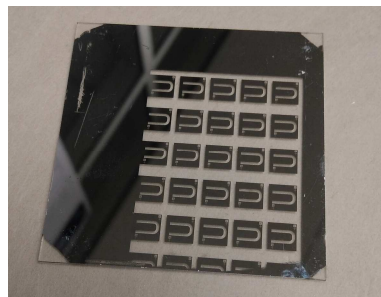
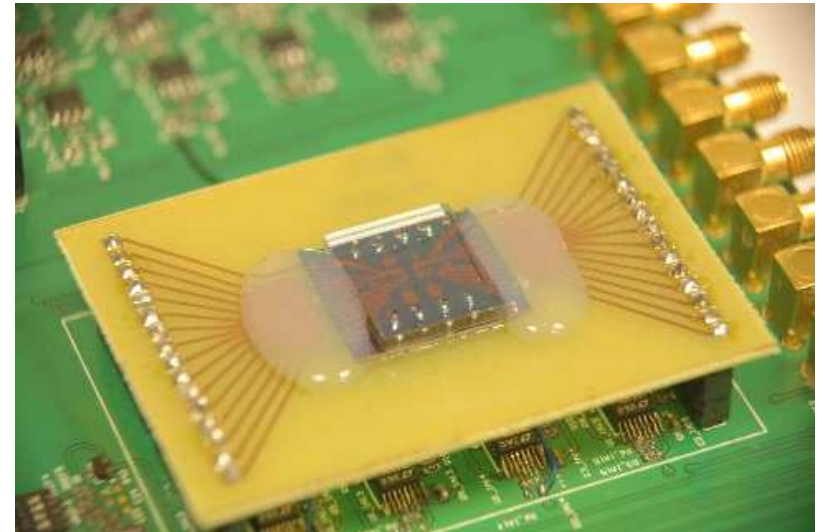
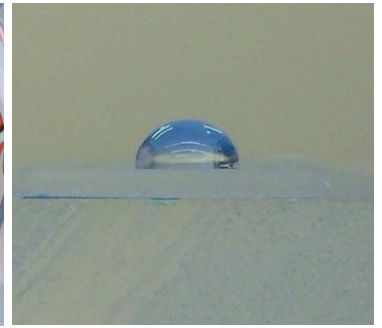
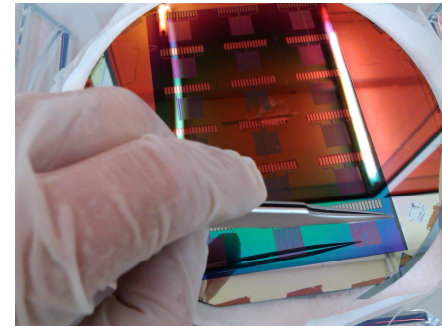
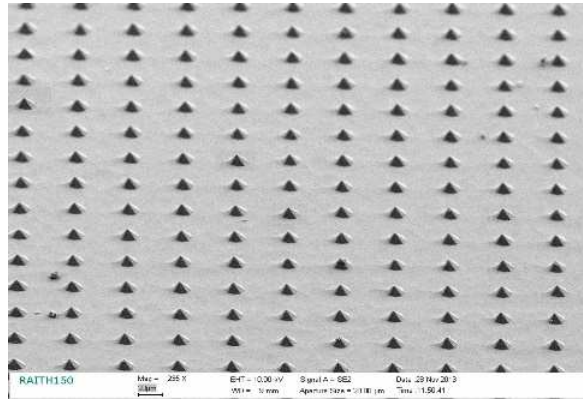
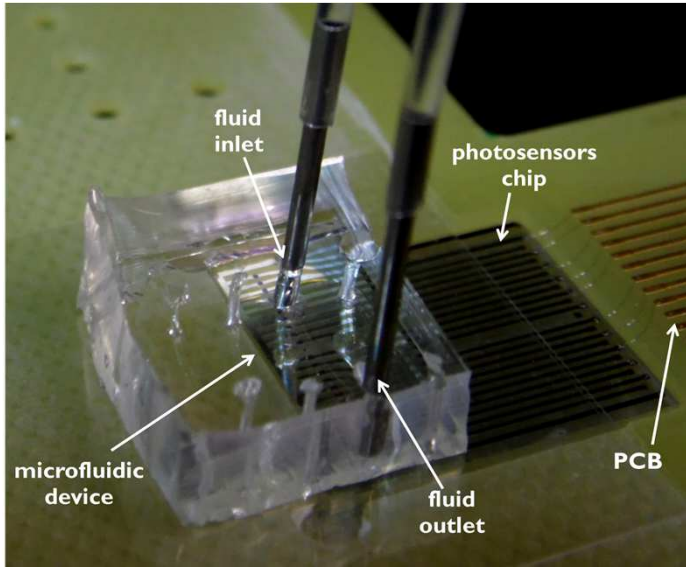
INESC MN

Microsystems and
Nanotechnologies

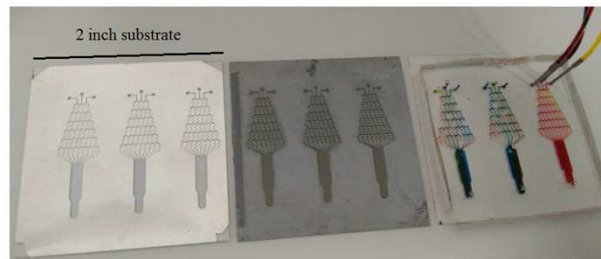
MICROFLUIDIC DEVICES AT INESC-MN



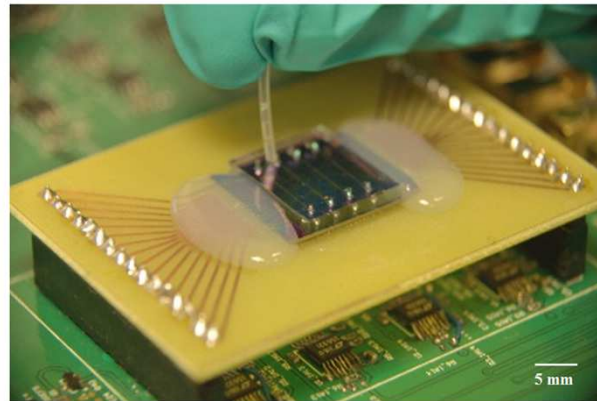
MICROFLUIDIC DEVICES AT INESC-MN



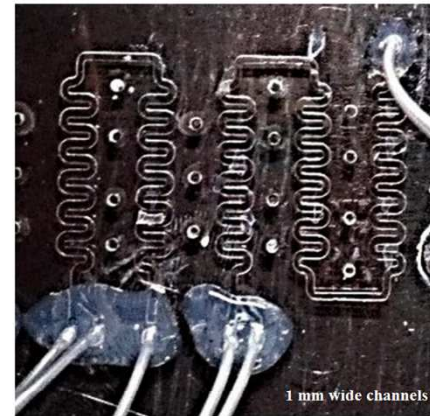
MICROFLUIDIC DEVICES AT INESC-MN



a) Hardmask, mold and PDMS microfluidic device



b) Integration of PDMS microfluidic device with magnetic sensors and electronics



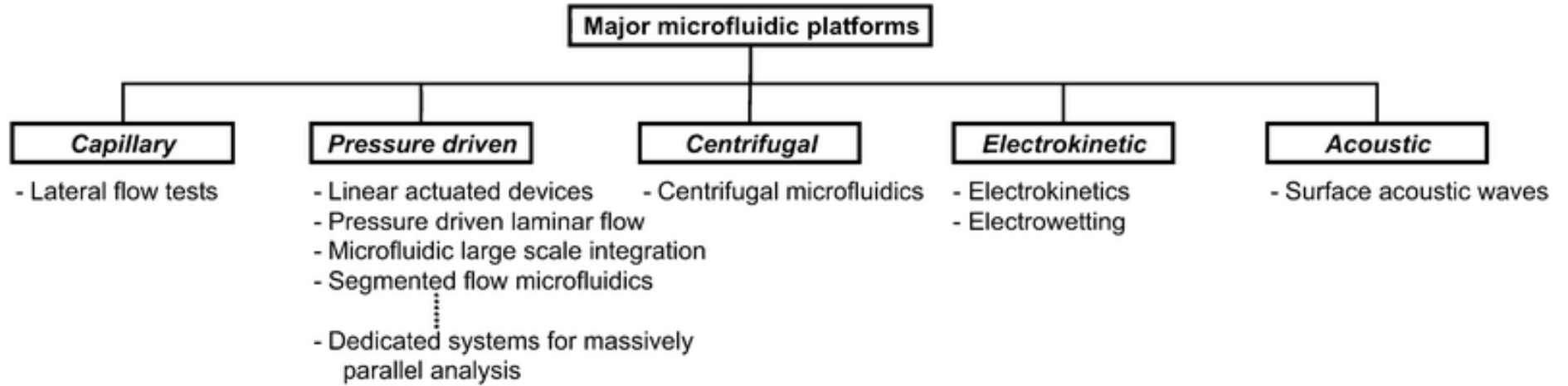
c) PMMA microfluidic device fabricated by 3D micromilling



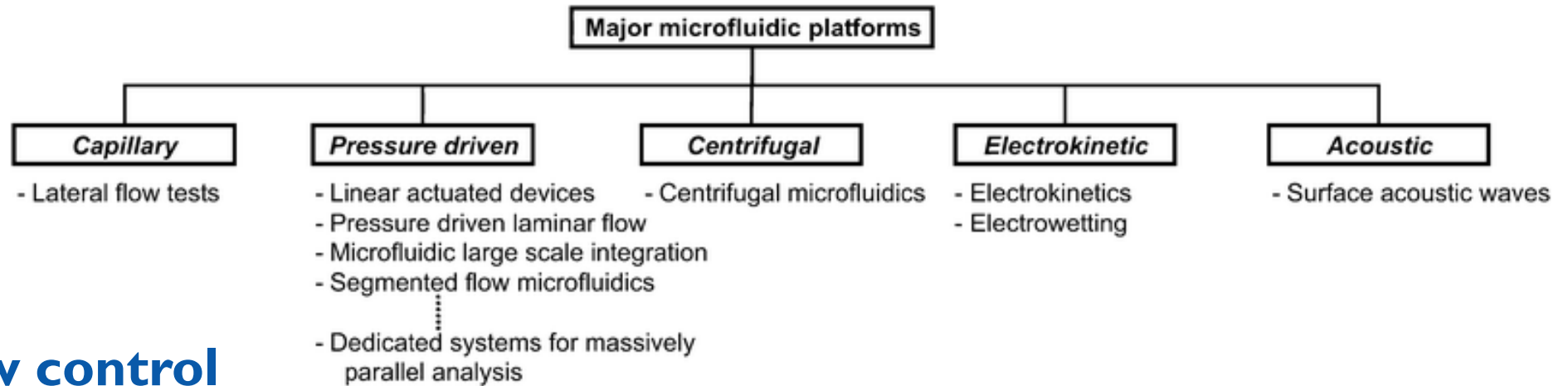
d) Microfluidics on paper

ACCURATE and TRACEABLE
measurements
of
micro-to-femto volumetric flow rates
are still
a technological challenge

FLOW CONTROL AND MEASUREMENT



FLOW CONTROL AND MEASUREMENT



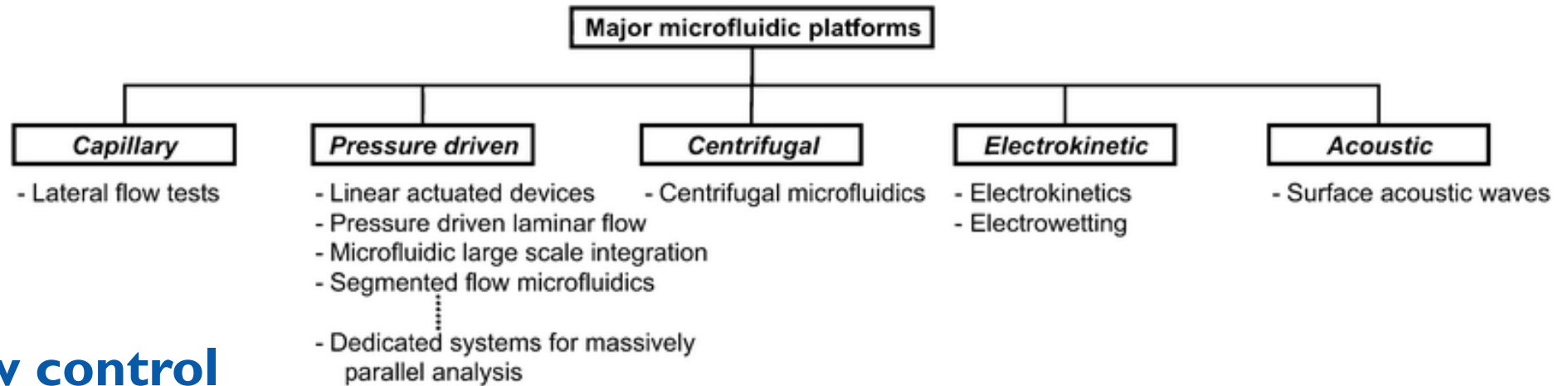
Flow control

- Magnetic actuation
- Quake valves
- Surface modification

Flow measurement

- μ PIV: fluorescence measurements of channel dimensions and flow velocity
- Spin valve sensors: chip integration of flow velocity measurements

FLOW CONTROL AND MEASUREMENT



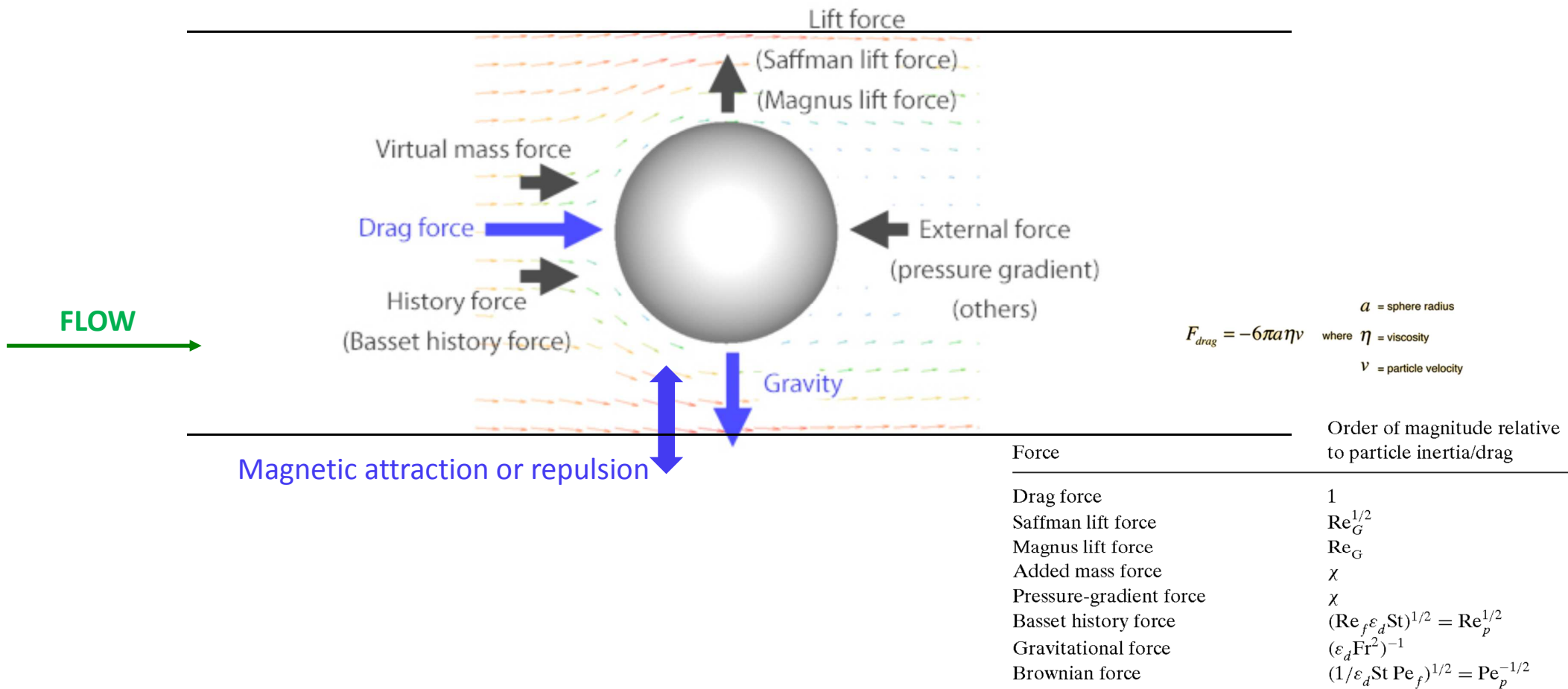
Flow control

- Magnetic actuation
- Quake valves
- Surface modification

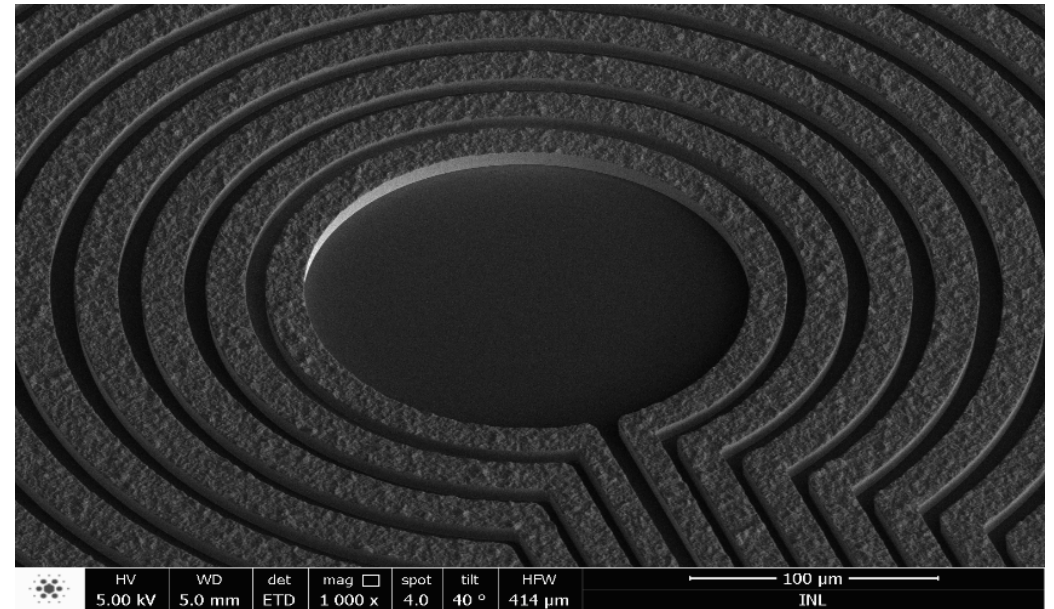
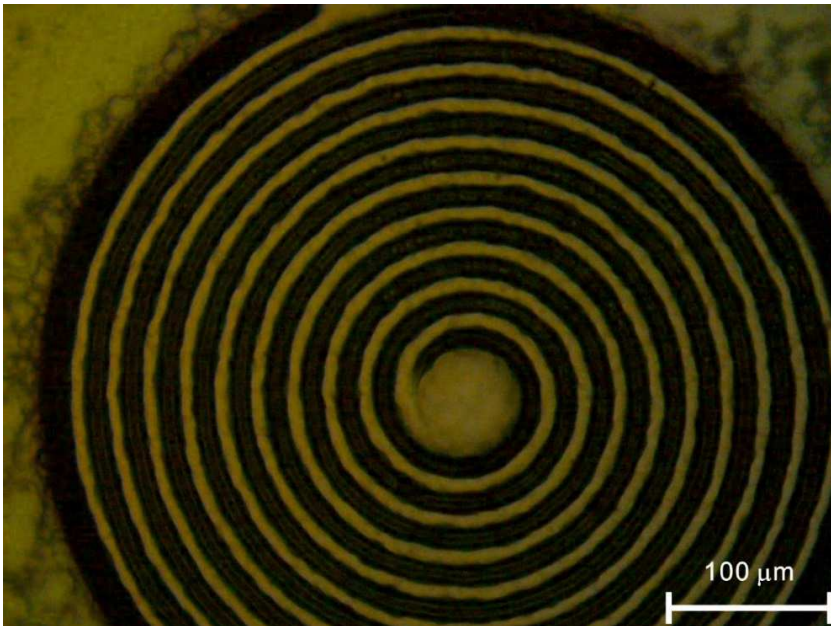
Flow measurement

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- Spin valve sensors: chip integration of flow velocity measurements

FLOW CONTROL AND MEASUREMENT

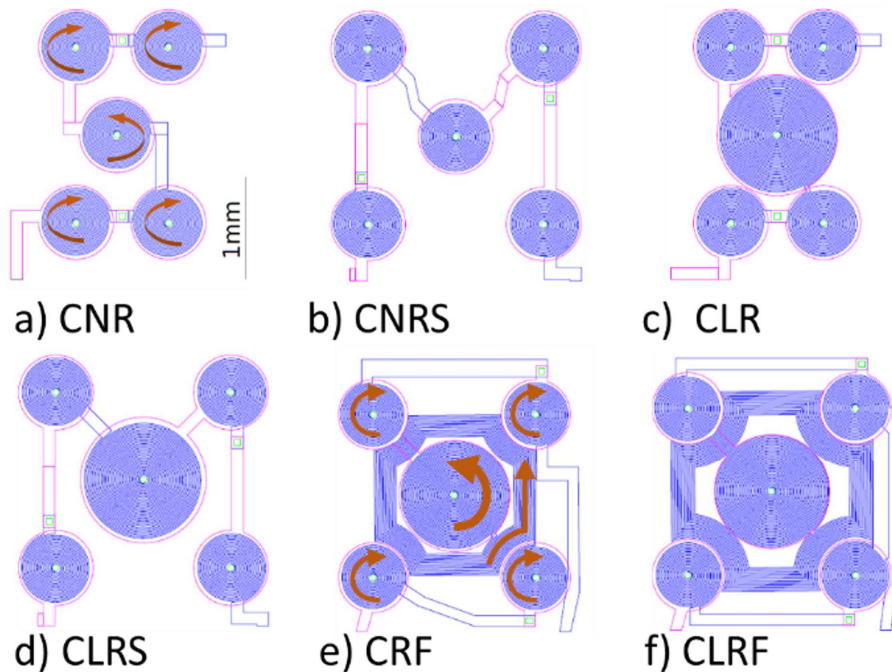


Electroplated Copper Coils

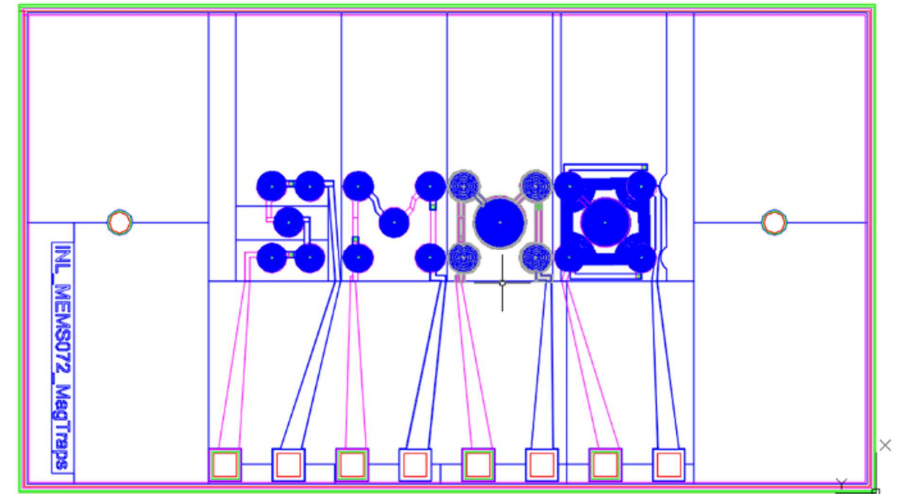


FLOW CONTROL AND MEASUREMENT

MEMT Design: 4 external coils in series and 1 central coil connected for opposite direction of trapping

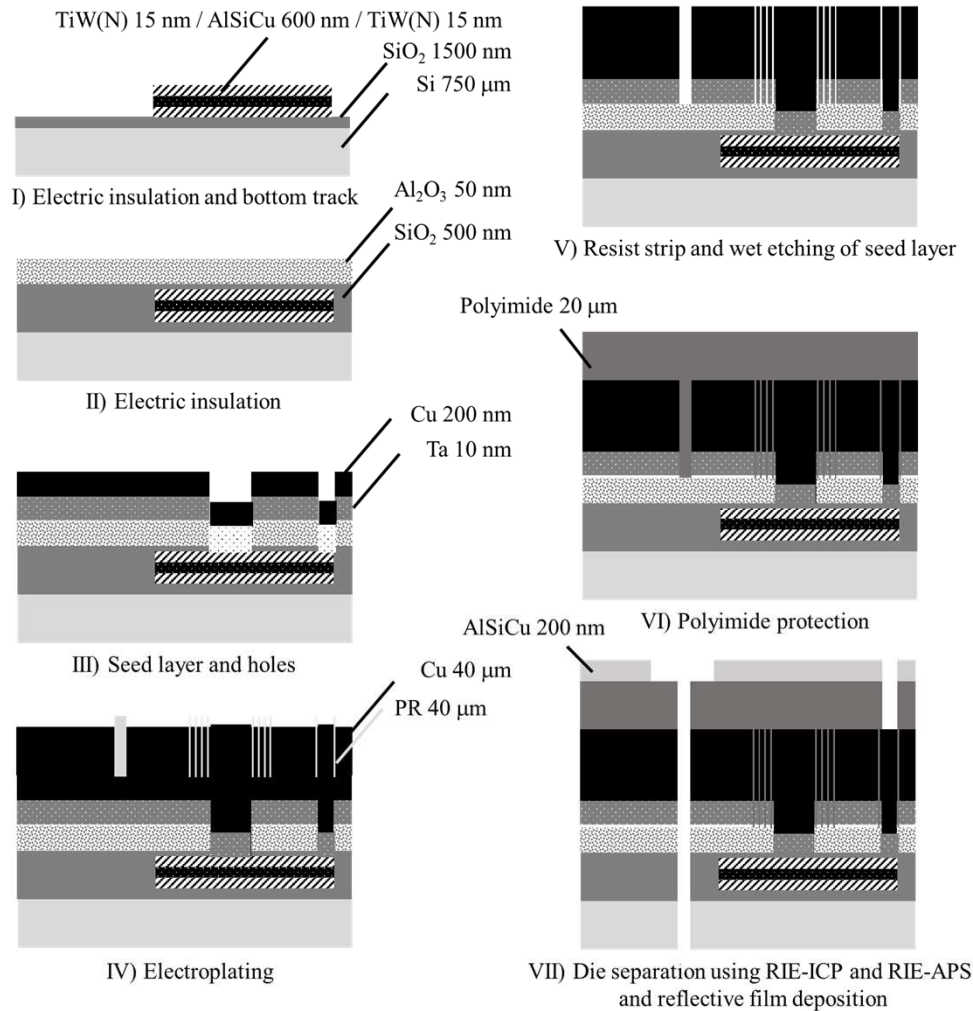


Central -C, Normal -N, Reversed -R, Squared -S, Large -L, Filling -F



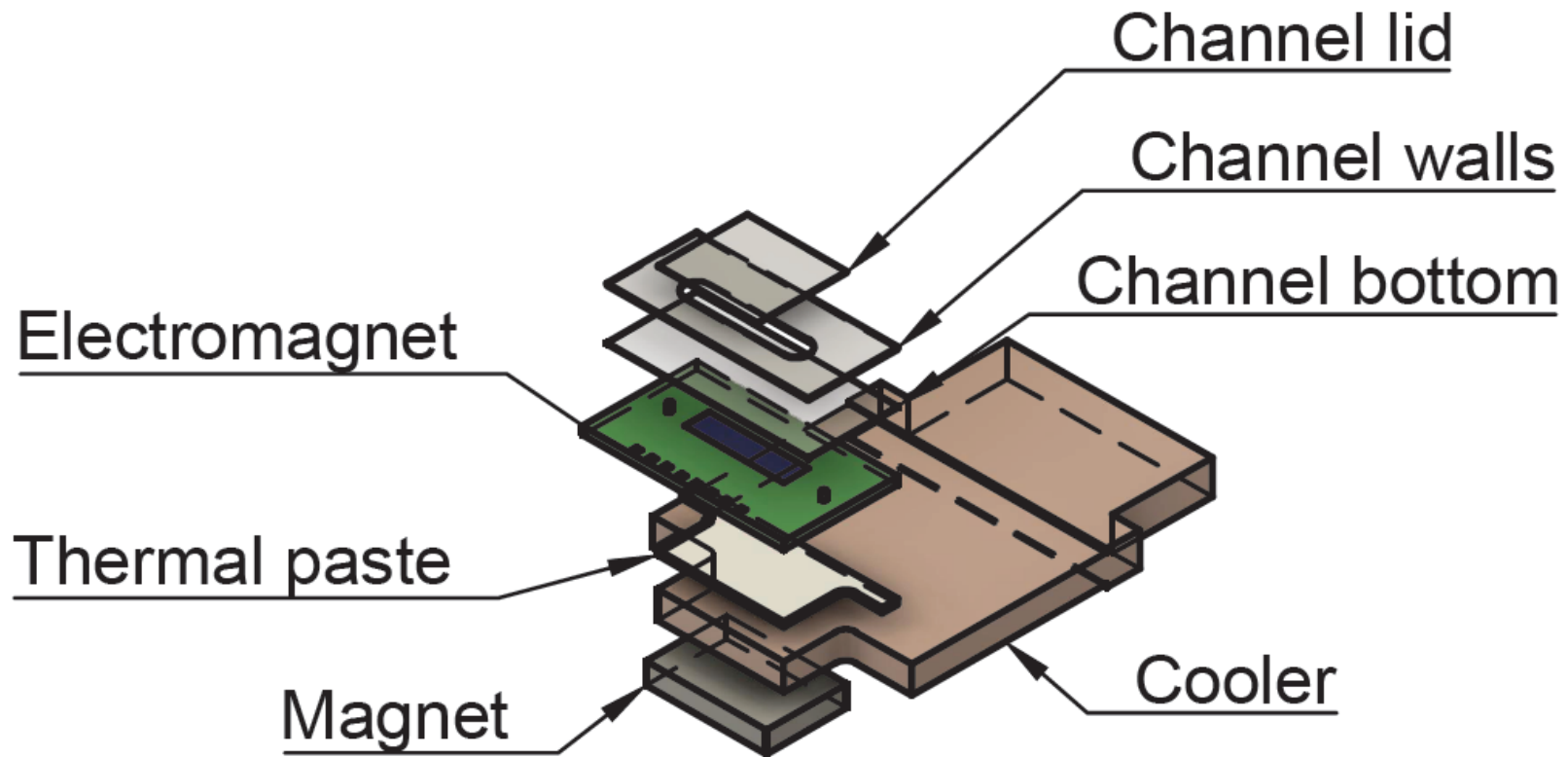
different designs were combined in 8 chips to a total of **56 chips in one 8" wafer**

FLOW CONTROL AND MEASUREMENT

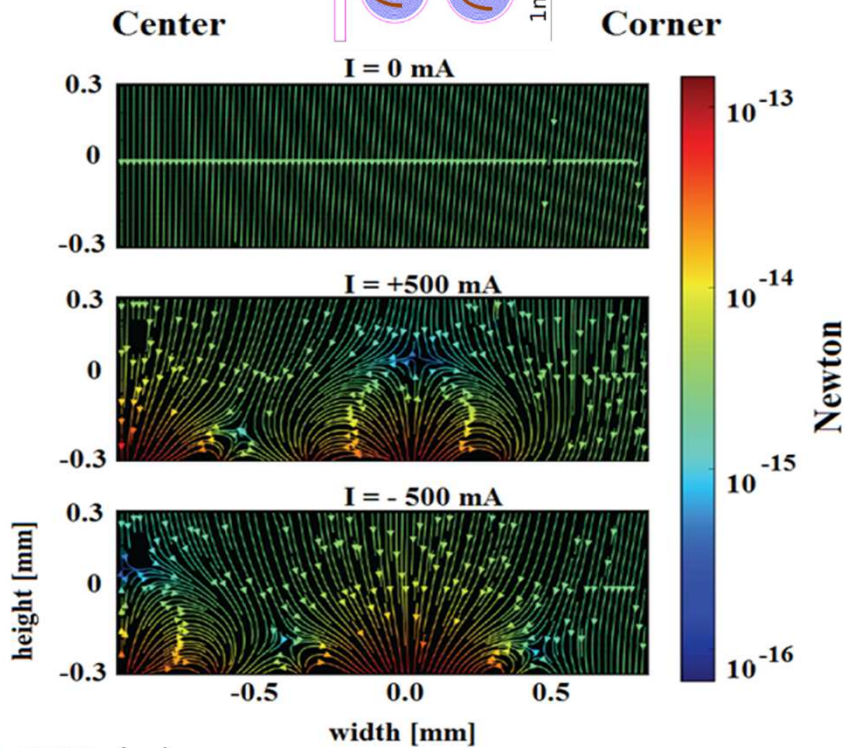
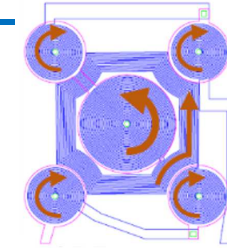
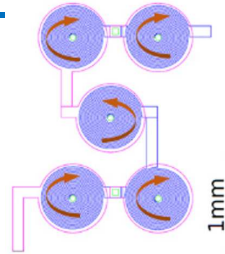


- 8" single side polished 725 μm-thick Si wafer
- isolation layer - SiO₂ (1500nm)
- Bottom track - TiW(N) (15nm)/Al (600nm)/TiW(N) (15nm)
- Optical lithography + ICP etch
- Isolation Layer - SiO₂ (500nm)
- Stopping layer for Ta seed layer etch - Al₂O₃ (50nm)
- Optical lithography, RIE etching (Al₂O₃ layer to SiO₂ layer) and RIE-APS etching (SiO₂ layer to TiW(N) layer).
- seed layer - sputtering of Ta (10nm) /Cu (200nm)
- patterning of 40 μm-thick photoresist preceded the Cu electroplating (Cu deposit on H₂SO₄, 280min, 5mA.cm⁻², 24°C, 12rpm agitation)
- Etch seed layer - (1:2 H₂O:Al etchant)
- Ta layer removed by XeF₂ dry vapor-phase etching
- spin coating polyamide (20 μm) for passivation, uniformization of surface topography and structural reinforcement
- Separation and holes - Si Etching, AlSiCu/TiW(N) wet etching
- Reflective coating of AlSiCu (200nm)

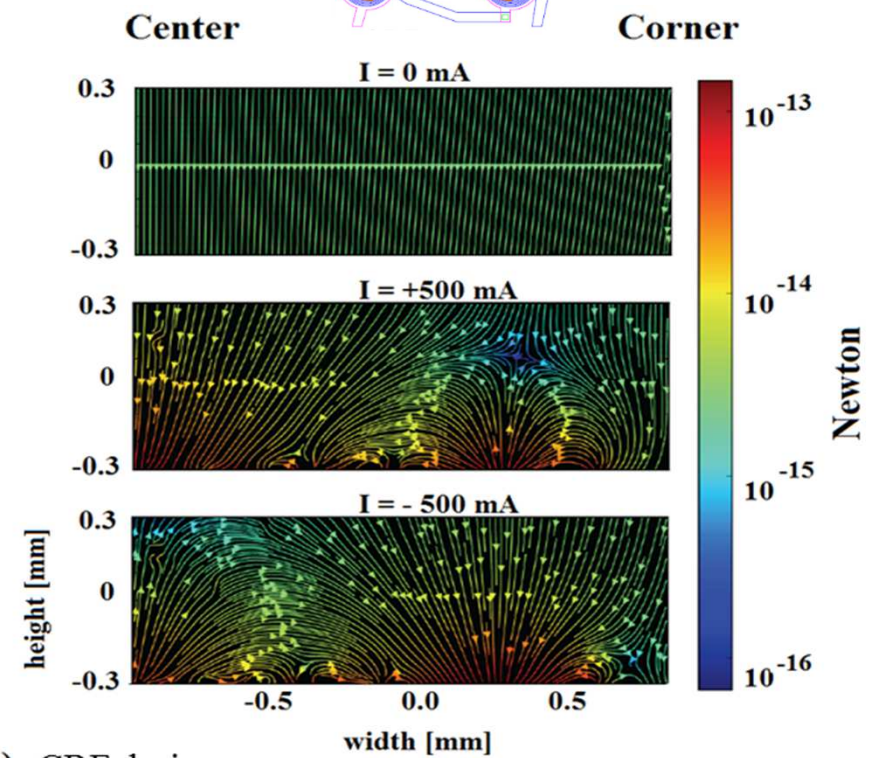
FLOW CONTROL AND MEASUREMENT



FLOW CONTROL AND MEASUREMENT



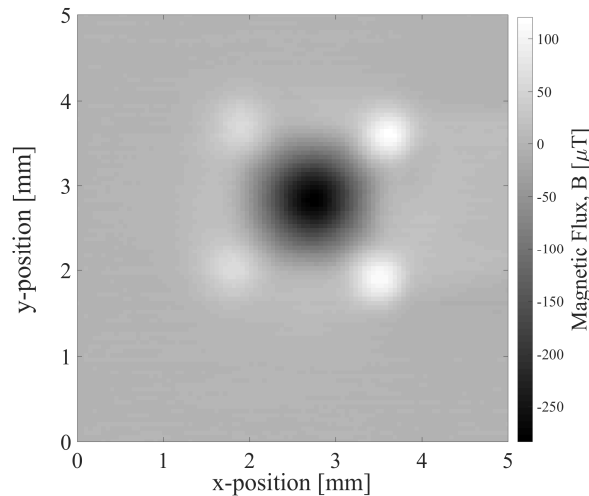
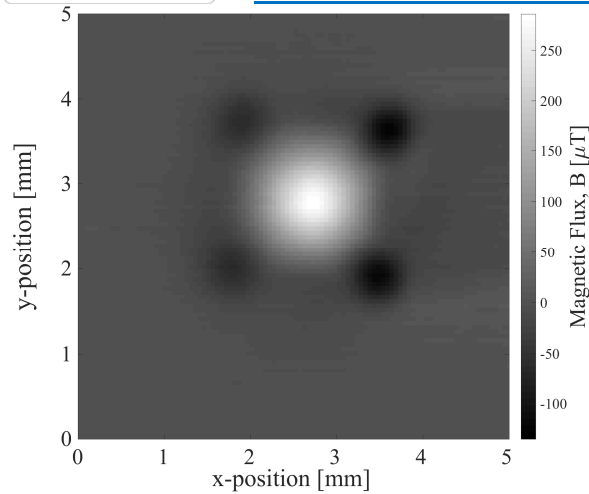
a) CNR design



b) CRF design

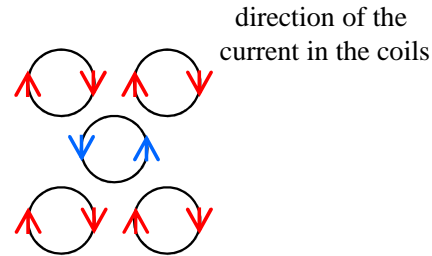
FLOW CONTROL AND MEASUREMENT

magnetoresistive scanner



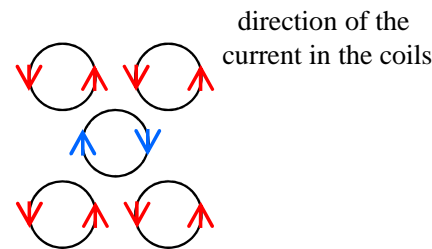
-30 mA

Sensor @ 200 μm from the chip surface



+30 mA

Sensor @ 200 μm from the chip surface



Magnetic Tunnel Junction (MTJ)
sensitivity $-26.4 \Omega \cdot \text{Oe}^{-1}$, dimension $58.5 \times 4 \mu\text{m}^2$

The vertical magnetic field over the **central coil** is **opposite** to the vertical field in the **4 outer coils**

- favorable for particle trapping and cell concentration - repulsion

The field generated by -30 mA was measured to range to +280 μT

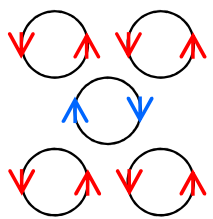
1000 mA actuation + PM field

- larger magnetic fields: up to 3000 μT
- sufficient to generate a magnetic force to deflect the MNP trajectories and trap them

MNP ACTUATION

16 pulses @ +750 mA

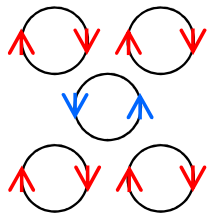
1 s ON + 2 s OFF + 1 s ON + ...



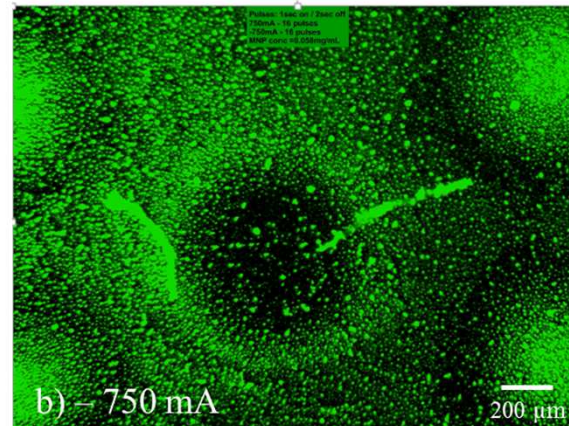
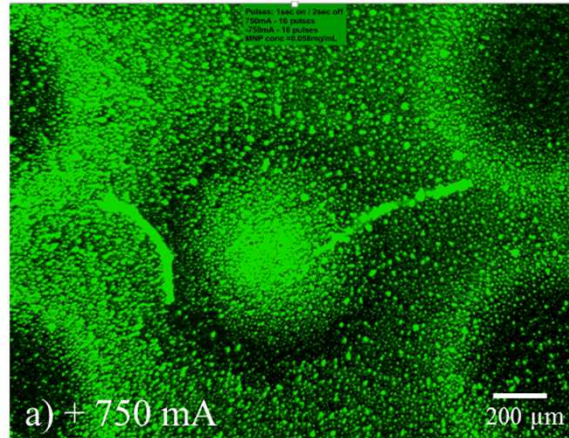
direction of the current in the coils

16 pulses @ -750 mA

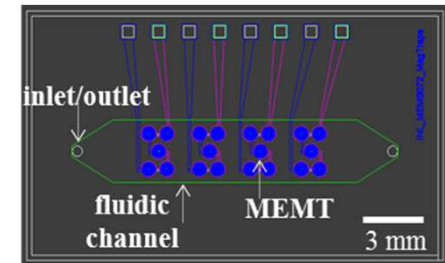
1 s ON + 2 s OFF + 1 s ON + ...



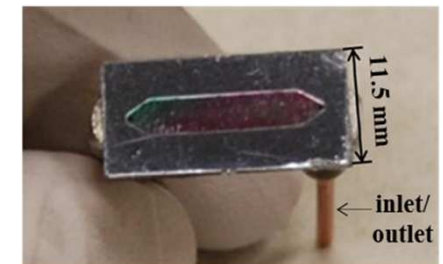
$$T_{surf,max} = 37 \text{ } ^\circ\text{C}$$



MEMT chip + microfluidic channel

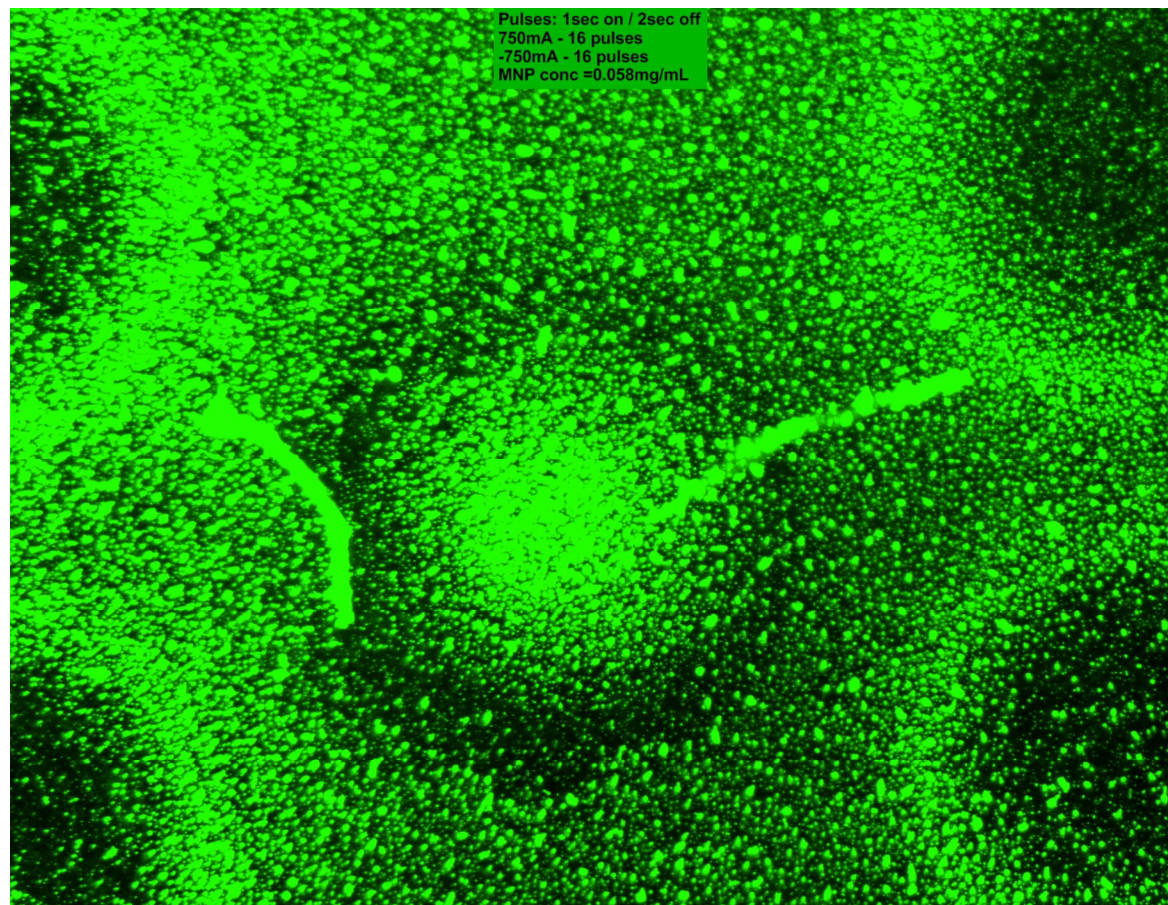


microchannel

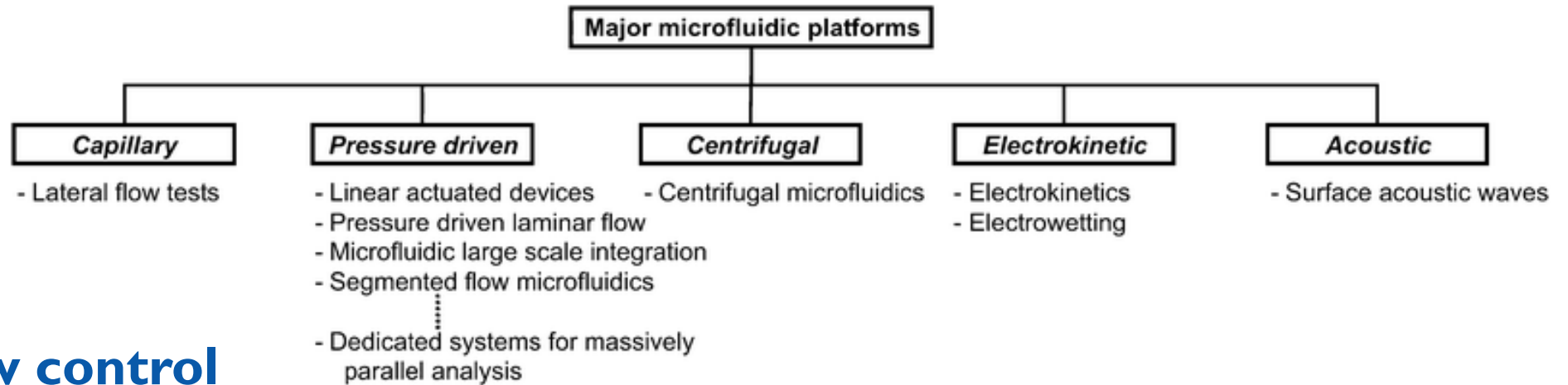


MNP concentration
0.058 mg.mL⁻¹

MNP ACTUATION



FLOW CONTROL AND MEASUREMENT



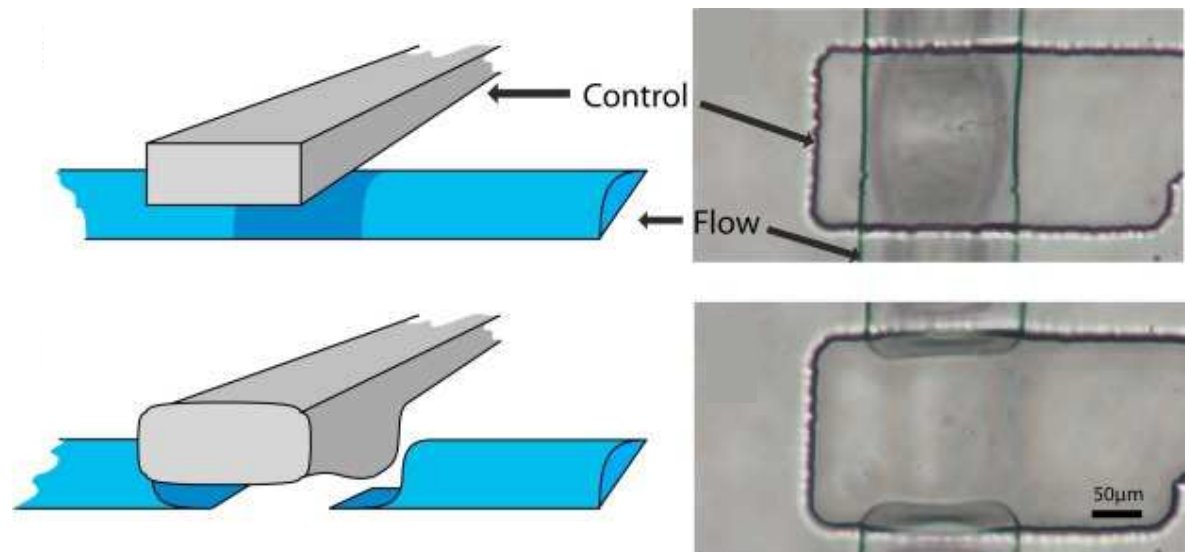
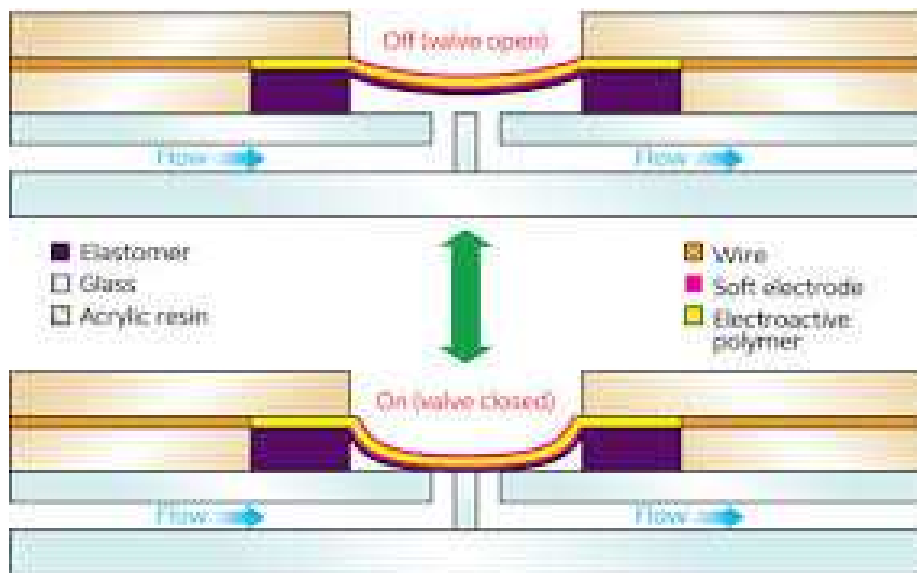
Flow control

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- Surface modification

Flow measurement

- μ PIV: fluorescence measurements of channel dimensions and flow velocity
- Spin valve sensors: chip integration of flow velocity measurements

QUAKE VALVES



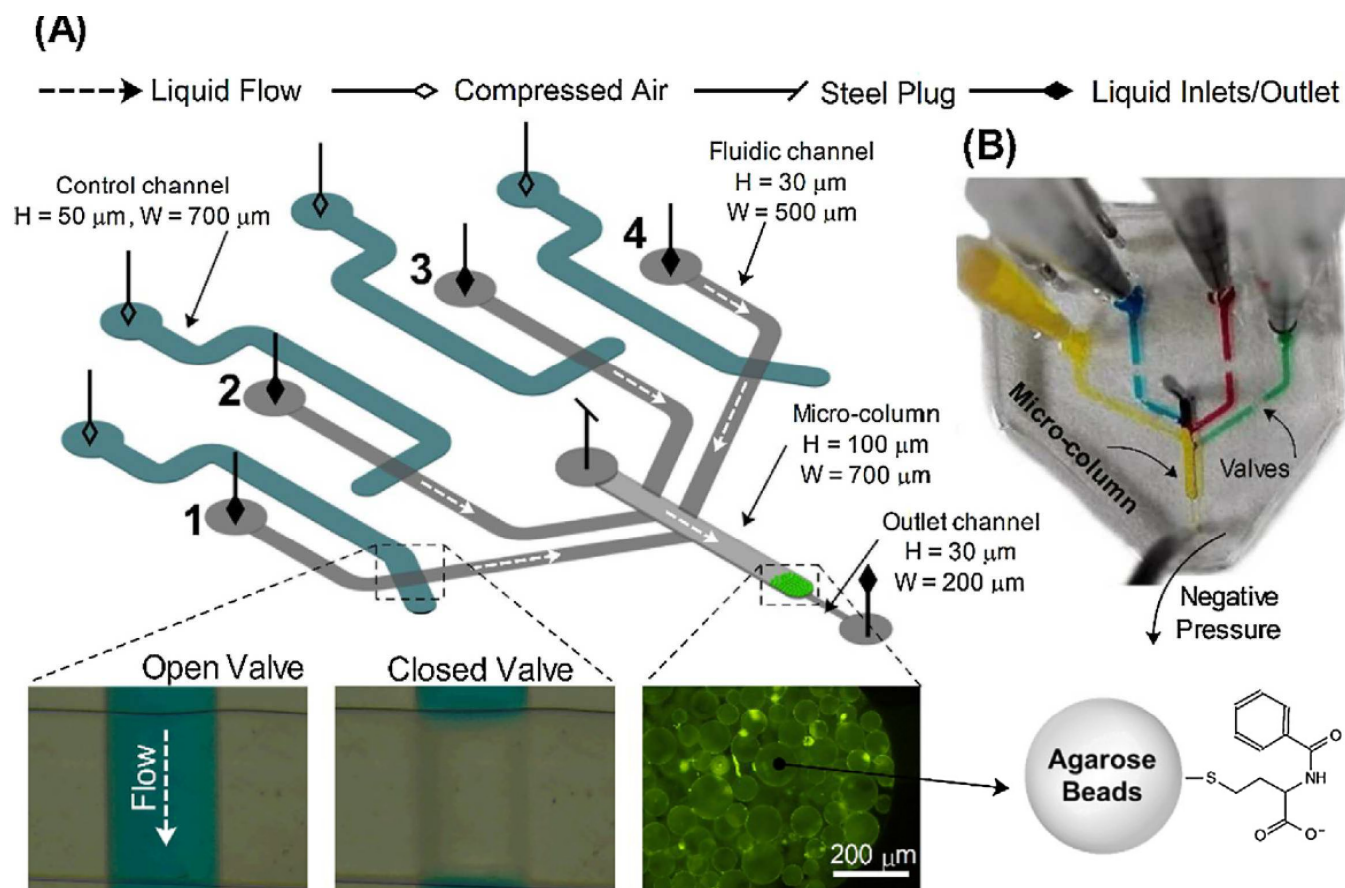


Fig. 2. Regenerable microfluidic structure comprising a main channel for bead packing and four fluidic channels for sequential liquid insertion controlled by integrated pneumatic valves. (A) Agarose beads functionalized with a chromatography multimodal ligand (Capto™ MMC) were packed in a micro-column and evaluated in their ability to capture a target monoclonal antibody labeled with Alexa 430 from a cell culture supernatant. Different solutions were flowed sequentially in an automatic manner by actuating the pneumatic valves. (B) PDMS structure showing the selective flow of 4 different colored solutions towards the micro-column. Liquid was flowed using pipette tips in the inlets and by applying a negative pressure at the outlet.



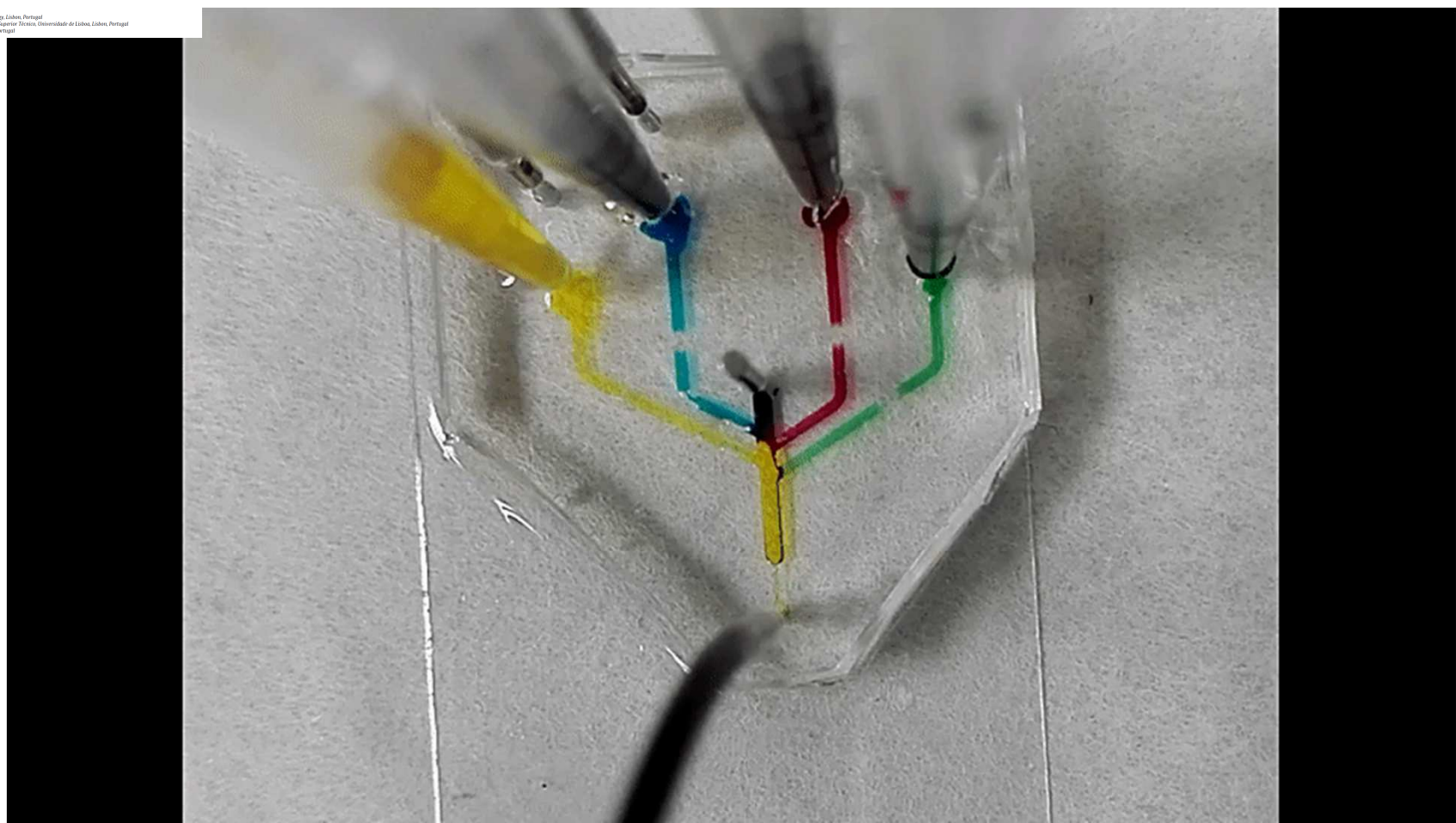
A regenerable microfluidic device with integrated valves and thin-film photodiodes for rapid optimization of chromatography conditions

I.F. Pinto^{a,b}, D.R. Santos^{a,b}, R.R.G. Soares^{a,b}, M.R. Aires-Barros^{b,c}, V. Chu^a,
A.M. Azevedo^{b,c,d}, J.P. Conde^{a,c,d}

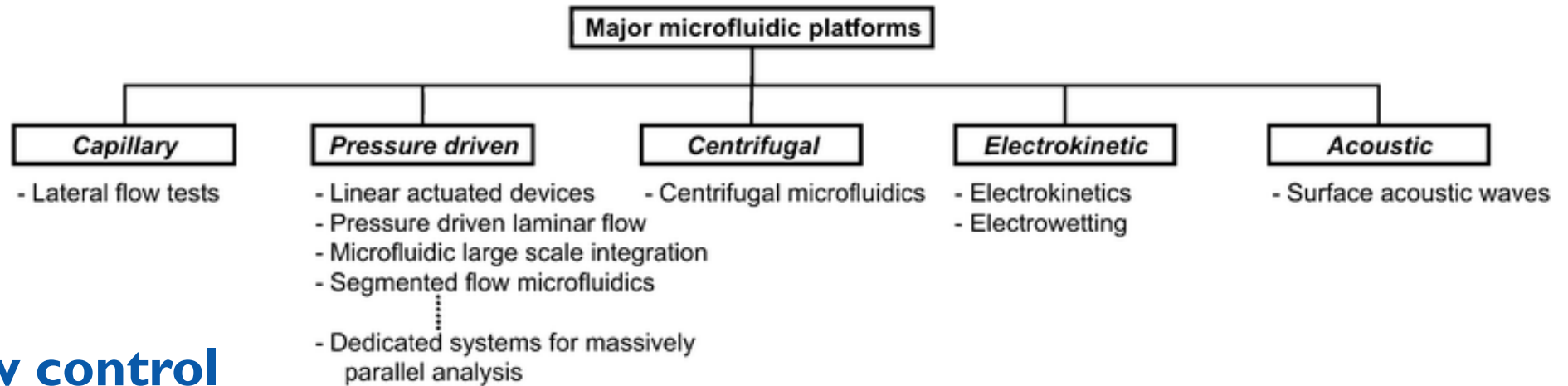
^aINES Microfluidics & Biotechnology and IC Institute of Nanoscience and Nanotechnology, Lisbon, Portugal

^bIBB – Institute for Bioengineering and Bioscience, Department of Biotechnology, Instituto Superior Técnico, Universidade de Lisboa, Lisbon, Portugal

^cDepartment of Biotechnology, Instituto Superior Técnico, Universidade de Lisboa, Lisbon, Portugal



FLOW CONTROL AND MEASUREMENT



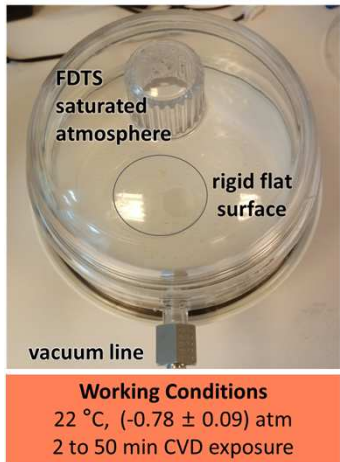
Flow control

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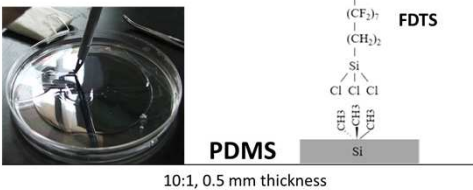
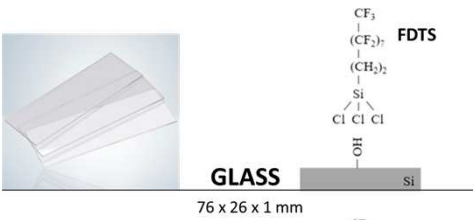
Flow measurement

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- Spin valve sensors: chip integration of flow velocity measurements

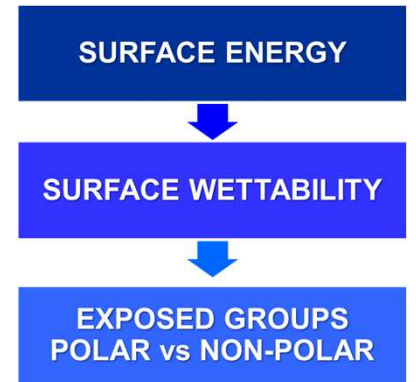
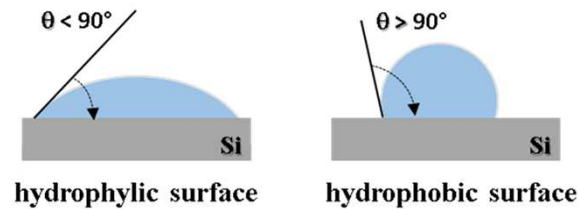
SURFACE MODIFICATION



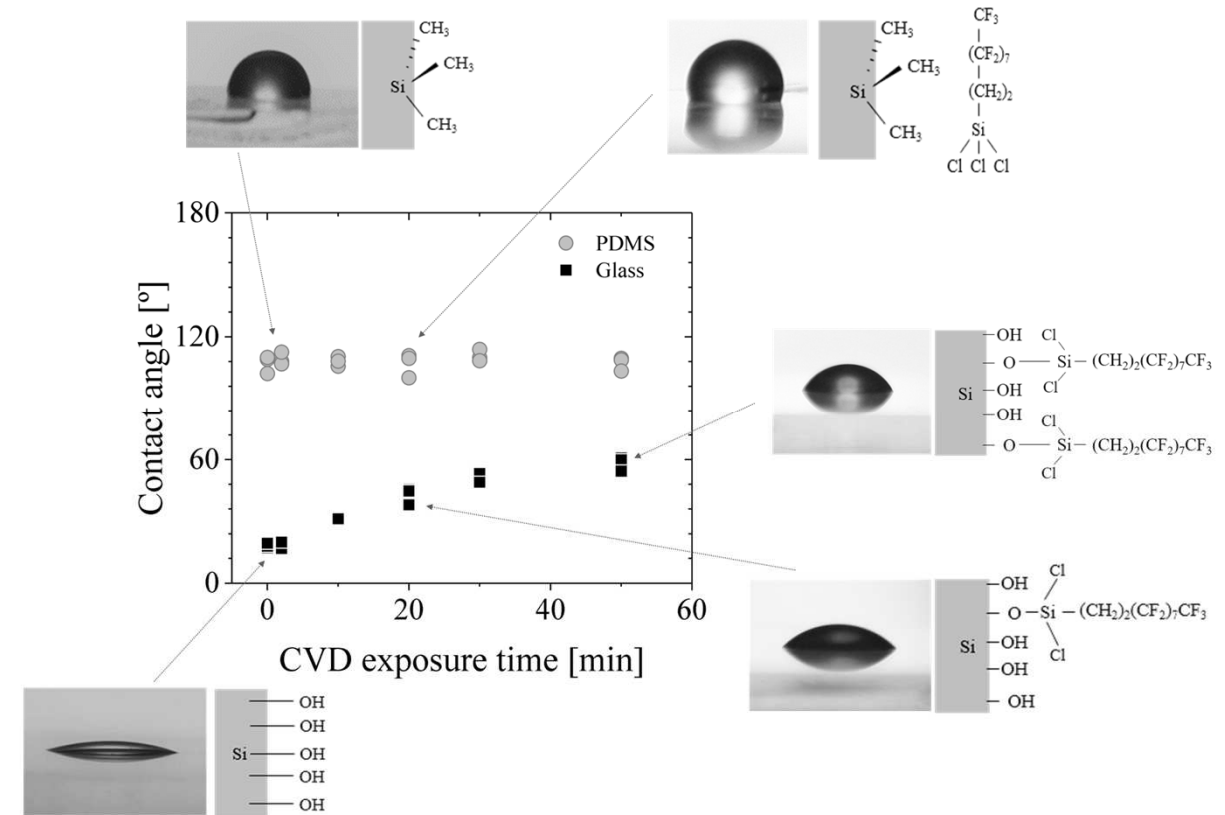
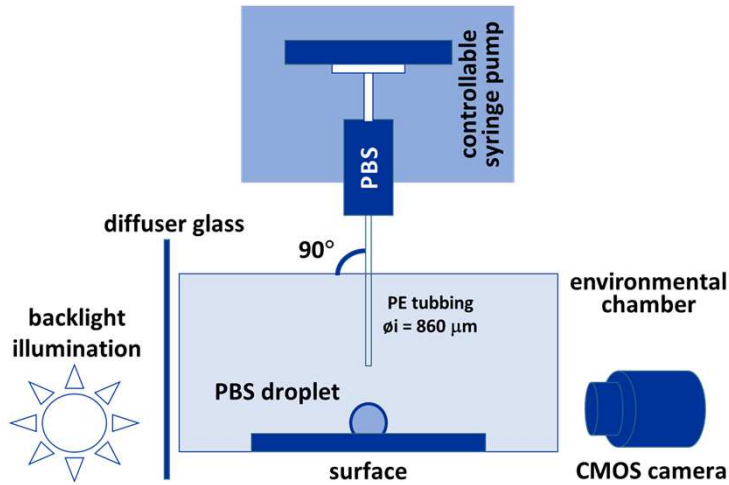
FDTS perFluoroDecylTrichloroSilane ($\text{CF}_3(\text{CF}_2)_7(\text{CH}_2)_2[\text{SiCl}_3]$)
 $M = 581.56 \text{ g/mol}$



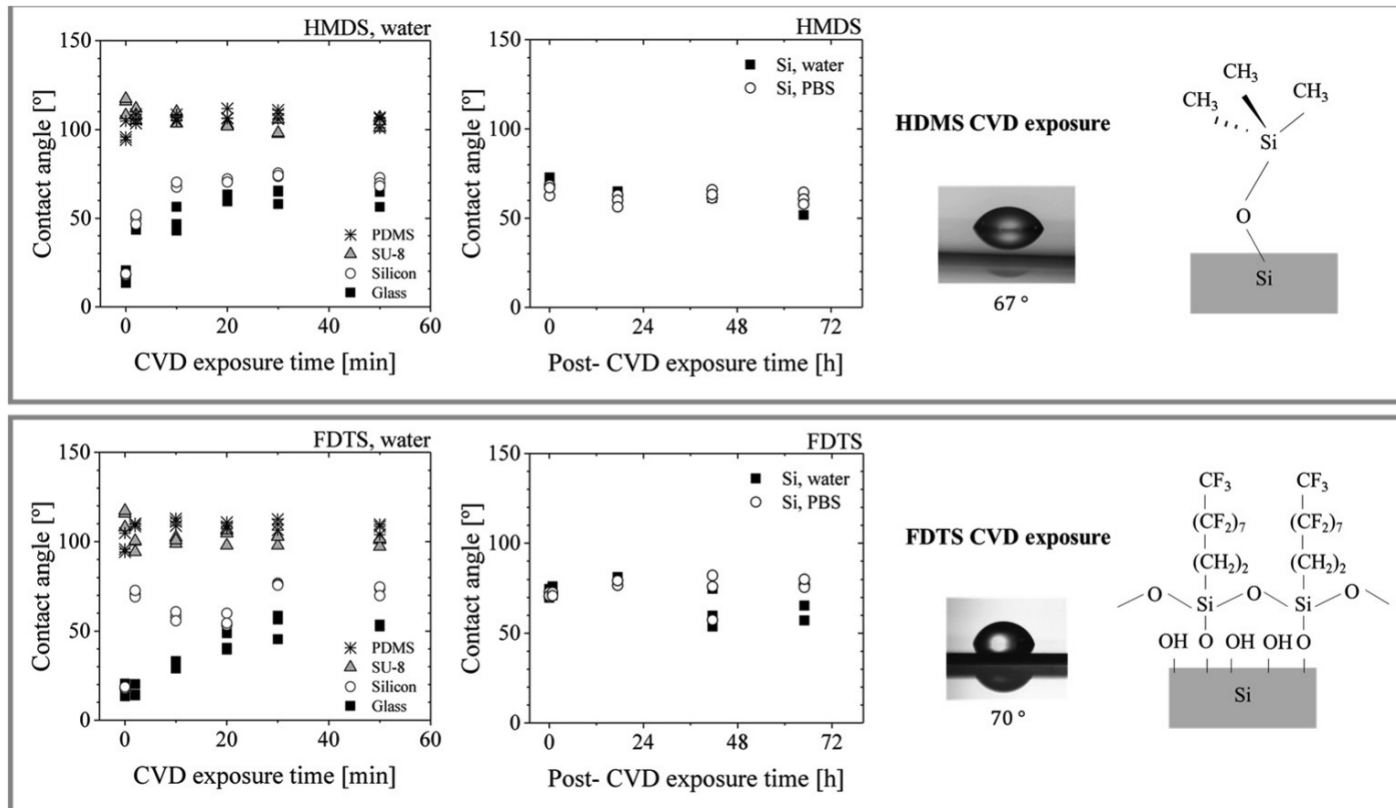
evaluation of contact angle translates the surface wettability



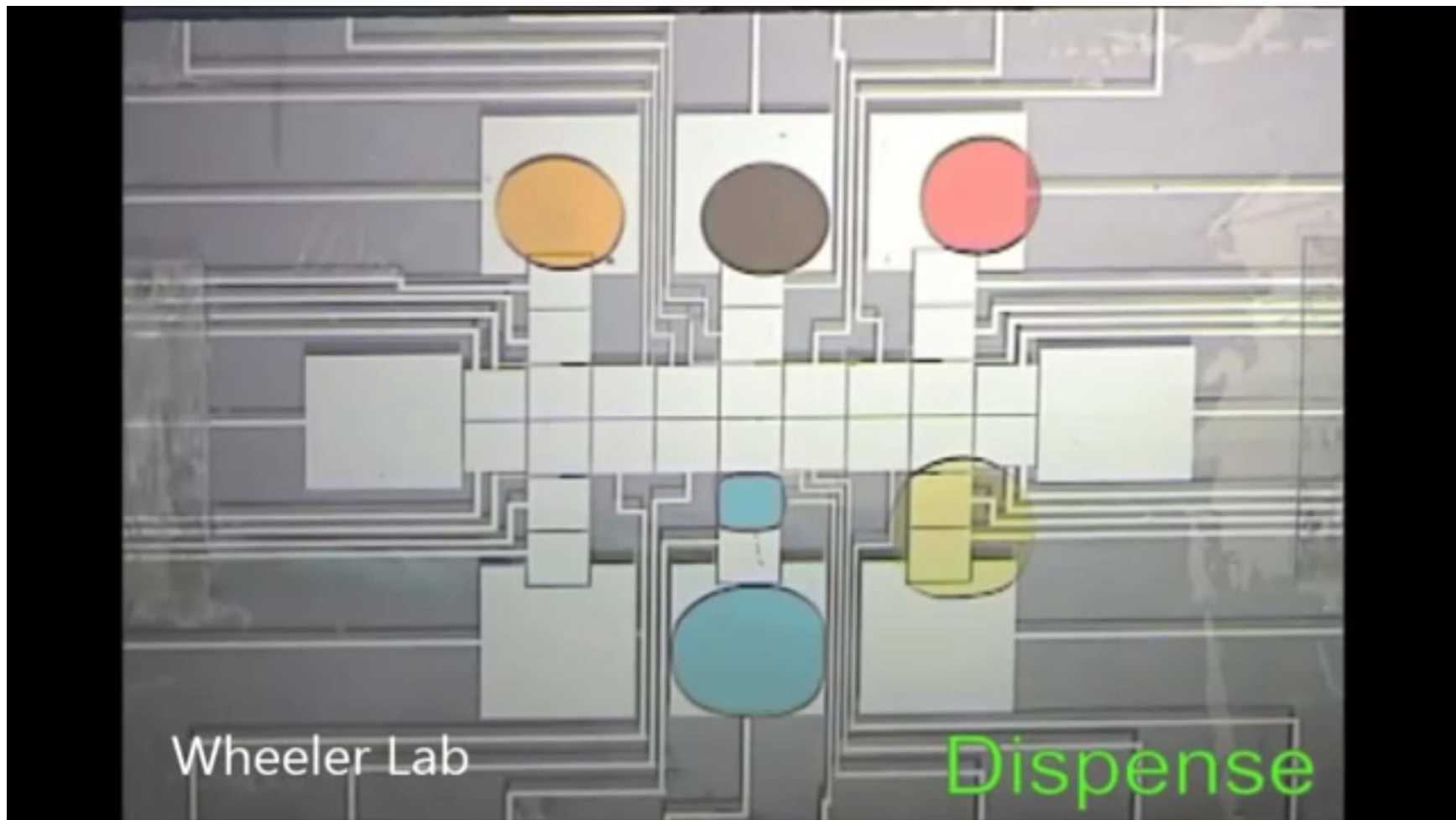
SURFACE MODIFICATION



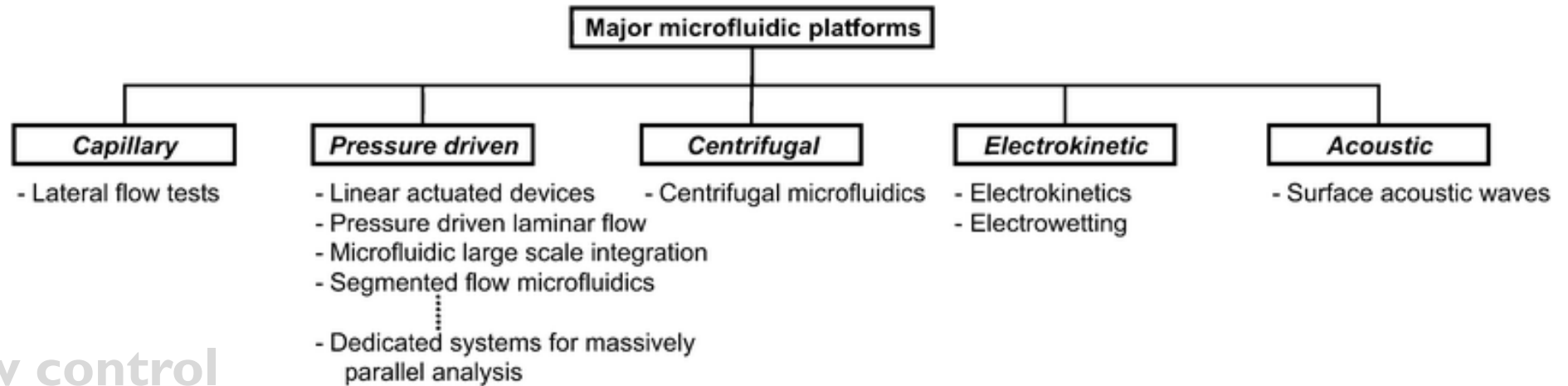
SURFACE MODIFICATION



Silverio V. *et al.* (2019) Surface wettability and stability of chemically modified silicon, glass and polymeric surfaces via room temperature chemical vapor deposition, *Colloids and Surfaces A: Physicochem. Eng. Aspects*, 570(5):210-217, DOI: 10.1016/j.colsurfa.2019.03.032



FLOW CONTROL AND MEASUREMENT



Flow control

- Magnetic actuation
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FLOW CONTROL AND MEASUREMENT

- working fluid is seeded with small fluorescent tracer particles
 - particles $\sim 1\mu\text{m}$ diameter
 - $\rho_{\text{particle}} \sim \rho_{\text{fluid}}$

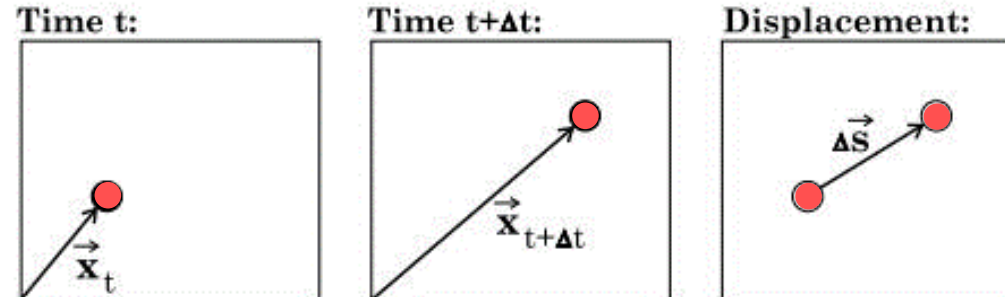
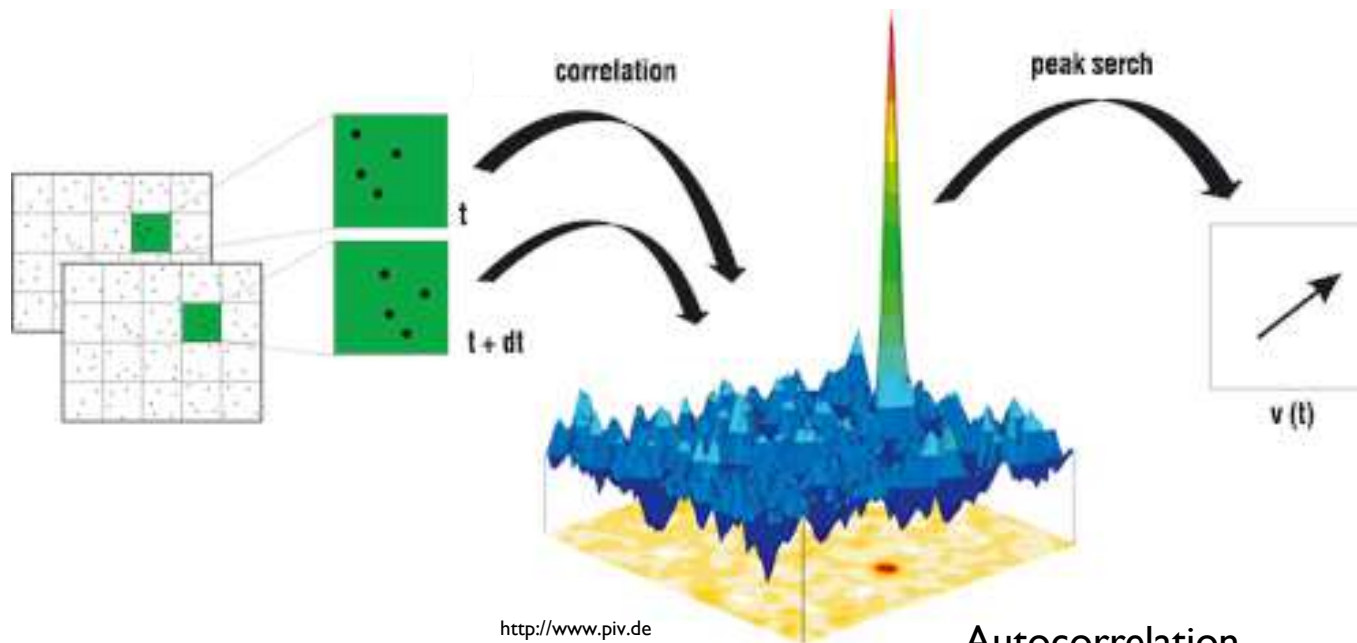


Figure : Left frame: particle position at time t ; Center frame: particle position at time $t + \Delta t$; Right frame: displacement vector Δs .

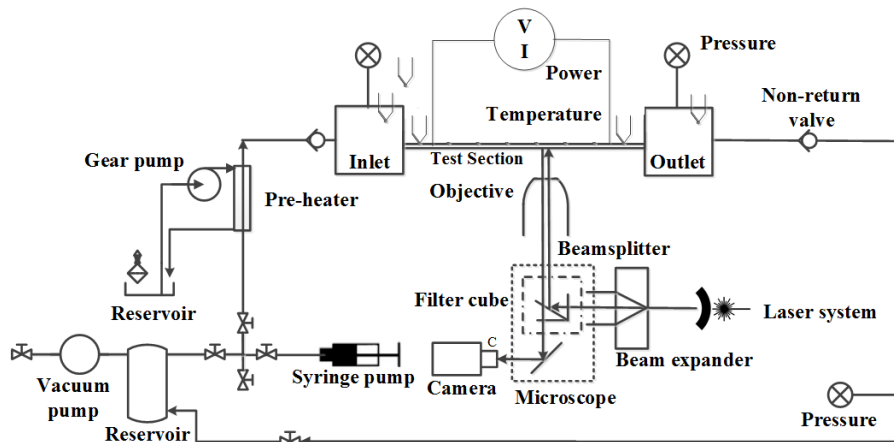
FLOW CONTROL AND MEASUREMENT



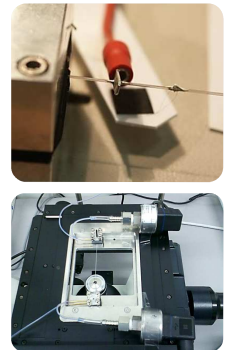
Autocorrelation
 Cross correlation
 Average correlation

FLOW CONTROL AND MEASUREMENT

PARTICLE IMAGE VELOCIMETRY – μ PIV



15 Hz μ PIV



HighSpeed μ PIV



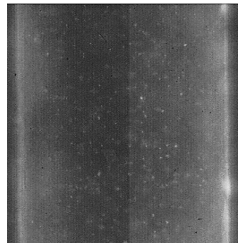
15 Hz μ PIV	HighSpeed μ PIV
Camera Dantec Dynamics FlowSense EO 2M, 44 Hz @ 1600 x 1200 pixel ² , CCD119 (charge-coupled device) sensor with pixel size = 7.41 μ m, 8/10 bit intensity resolution	Camera LaVision HighSpeedStar 4G, 2 kHz @ 1024 x 1024 pixel ² , CMOS (complementary metal-oxide semiconductor) imaging sensor with pixel size = 17 μ m, 12 bit intensity resolution
Laser New Wave Research dual cavity Nd:YAG Solo II-15 emitting at $\lambda = 532$ nm, repetition rate = 15 Hz, E _{15Hz} = 30 mJ	Laser Litron dual cavity Nd:YLF laser LDY301 PIV emitting at $\lambda = 527$ nm, repetition rate = 0.2 – 20 kHz, E _{1kHz} = 10 mJ
Inverted Microscope Leica DM ILM	Inverted Laboratory Microscope Leica DM IL LED
Software: Flowmanager V4.0, Dynamic Studio. Synchronization: National Instruments hardware	Software: Davis 8.2.0. Synchronization: LaVision Synchronization: Highspeed controller

- gradient parameters that can be derived from the flow velocity information resulting from 2D-PIV, and aid in quantification and interpretation of the flow phenomena studied

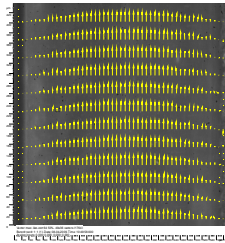
Parameter	Stands for:	Equation
Vorticity	Rotationality of the fluid	$\omega = \partial v / \partial x - \partial u / \partial y$
Shear rate	Strength of velocity gradient perpendicular to the local velocity ('sliding of adjacent water layers')	$h = \partial v / \partial x + \partial u / \partial y$
Strain rate	Strength of velocity gradient in the direction of the local velocity ('acceleration within one water layer')	$e = \partial u / \partial x - \partial v / \partial y$
Divergence	Strength of out-of-plane flow rate (water leaving or entering the illuminated plane)	$\Theta = \partial u / \partial x - \partial v / \partial y$
Vortex locator	Finds centre of vortex (e.g. through discriminant for complex eigenvalues)	

FLOW CONTROL AND MEASUREMENT

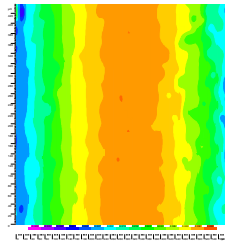
raw image



velocity vector field

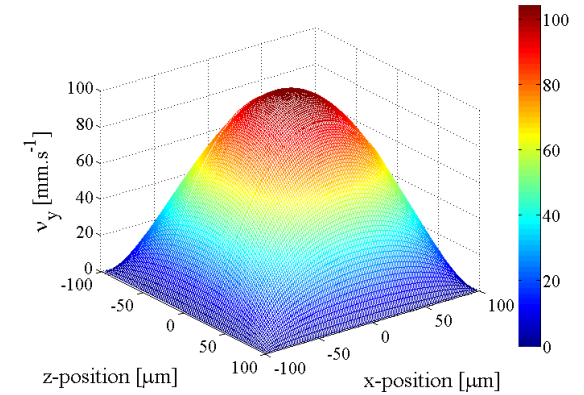
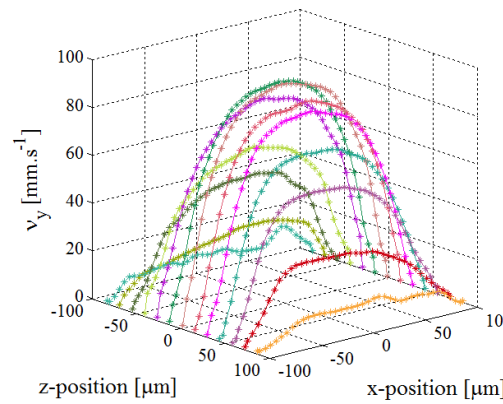
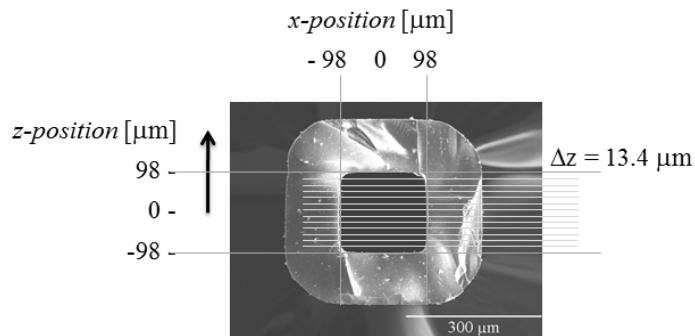


isovelocity magnitude



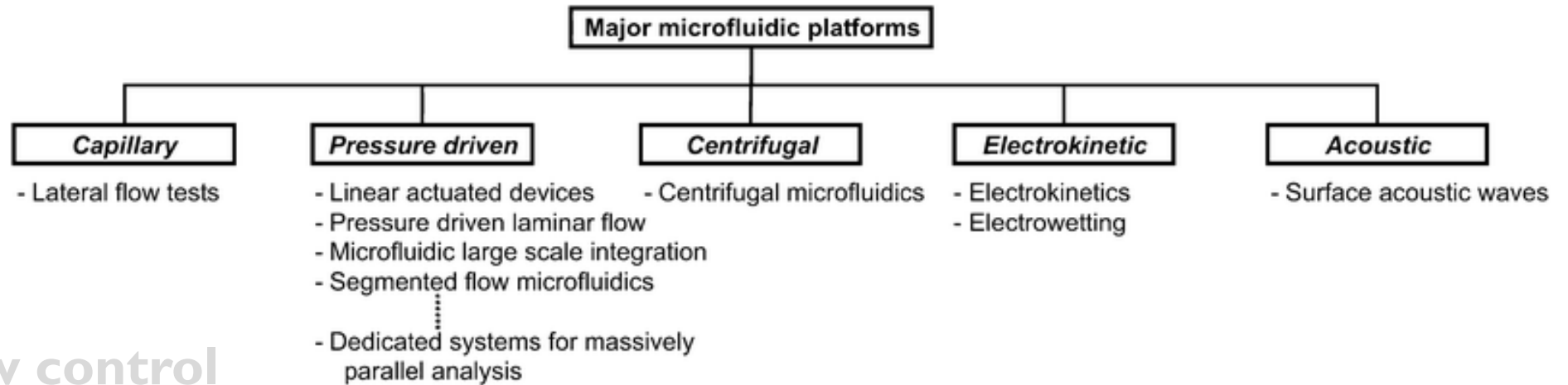
$$-\frac{W}{2} \leq x \leq \frac{W}{2}, -\frac{H}{2} \leq z \leq \frac{H}{2}$$

$$v_y = \frac{16 \left(\frac{H}{2}\right)^2}{\mu \pi^3} \left(-\frac{dp}{dy}\right) \sum_{i=1,3,5,\dots}^{\infty} (-1)^{\frac{i-1}{2}} \left[1 - \frac{\cosh\left(\frac{i\pi x}{H}\right)}{\cosh\left(\frac{i\pi W}{2H}\right)} \right] \frac{\cos\left(\frac{i\pi z}{H}\right)}{i^3}$$



4.7 % deviation

FLOW CONTROL AND MEASUREMENT



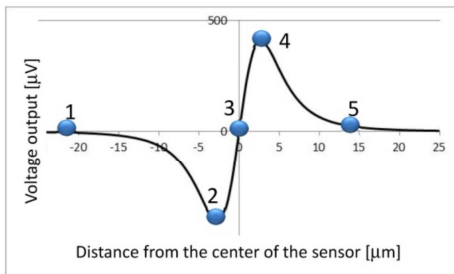
Flow control

- Magnetic actuation
- Quake valves
- Surface modification

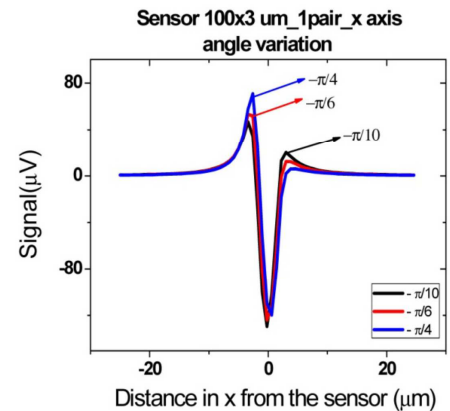
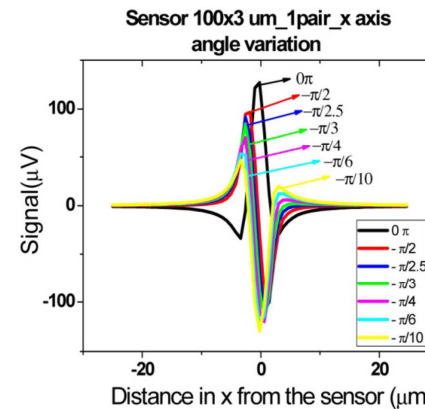
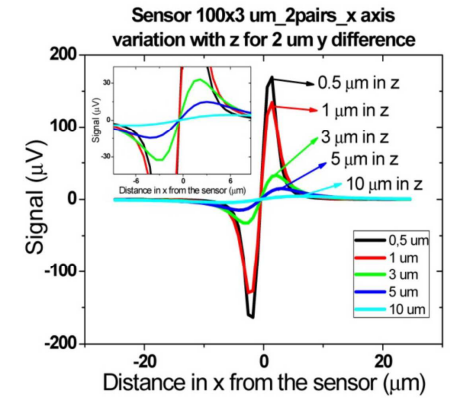
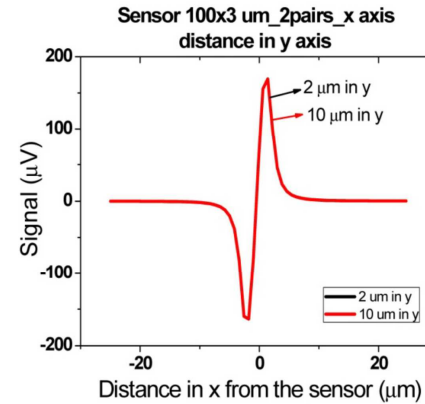
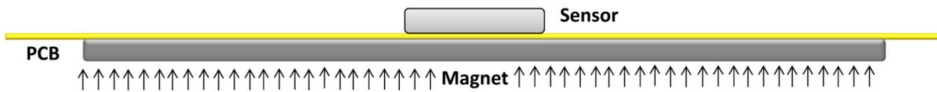
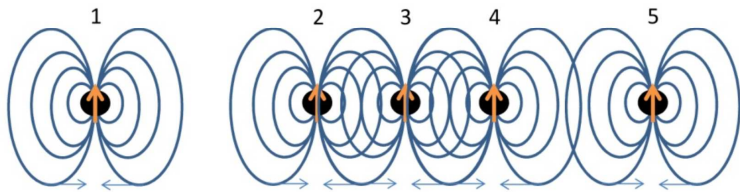
Flow measurement

- μ PIV: fluorescence measurements of channel dimensions and flow velocity
- Spin valve sensors: chip integration of flow velocity measurements

MAGNETIC FLOW CYTOMETRY



Magnet's field direction →
 Particle/Cell magnetic alignment with the magnetic field →
 Particle's magnetic fringe field (horizontal component) →



SPIN VALVES FOR VELOCITY MEASUREMENTS

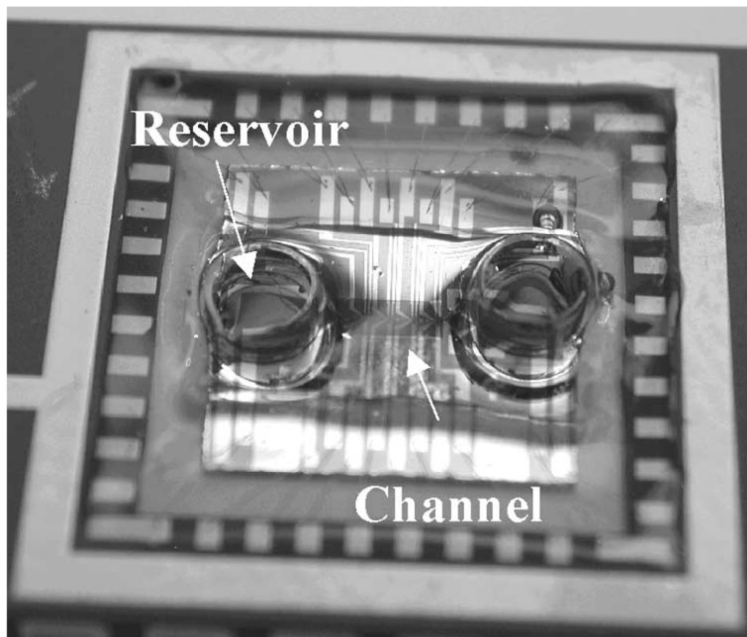


Fig. 1. Spin valve sensor chip with a bonded 1-mm-wide microchannel mounted in a chip-carrier.

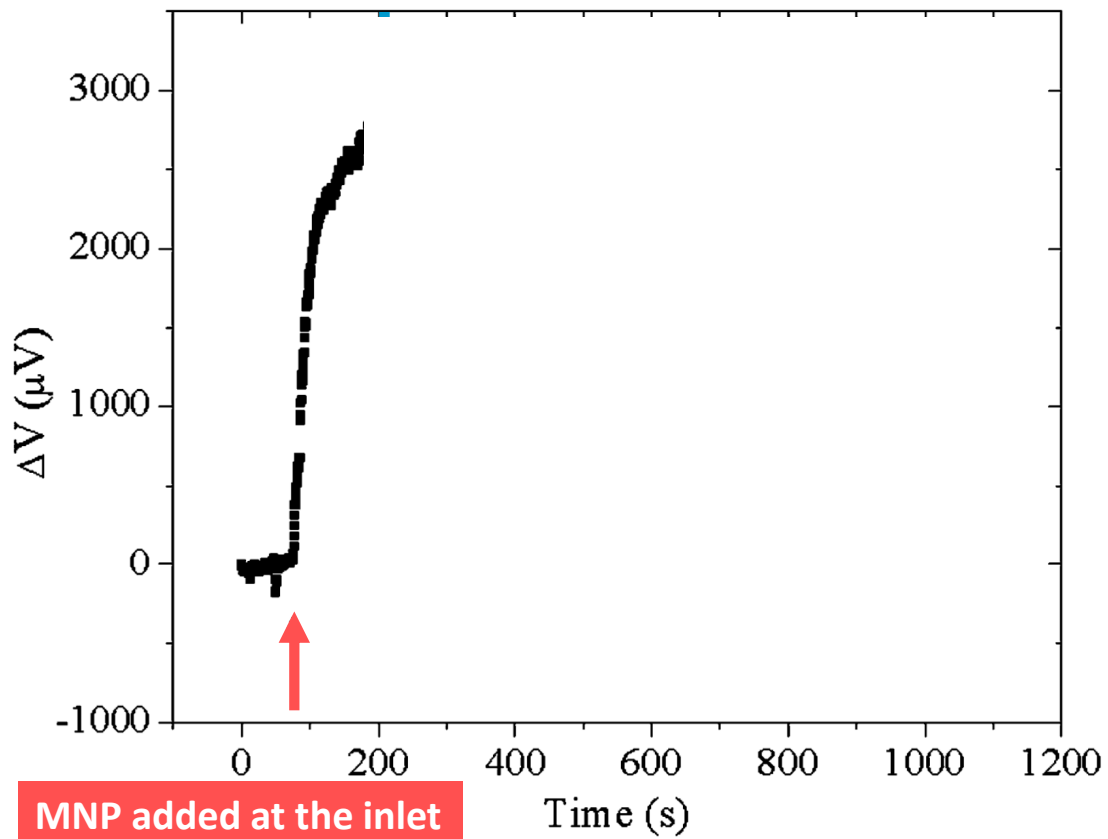
The spin valve stack was fabricated by an ion beam deposition system on a 3 in. Si wafer and has the structure Ta 20 Å/NiFe 30 Å/CoFe 25 Å/Cu 26 Å/CoFe 25 Å/MnIr 60 Å/Ta 30 Å/TiW(N) 150 Å. As deposited the spin valve coupon sample has a magnetoresistance ratio (MR) of $\sim 7.5\%$. The sensors were defined by standard photolithographic techniques and by ion milling.



250 nm superparamagnetic particles

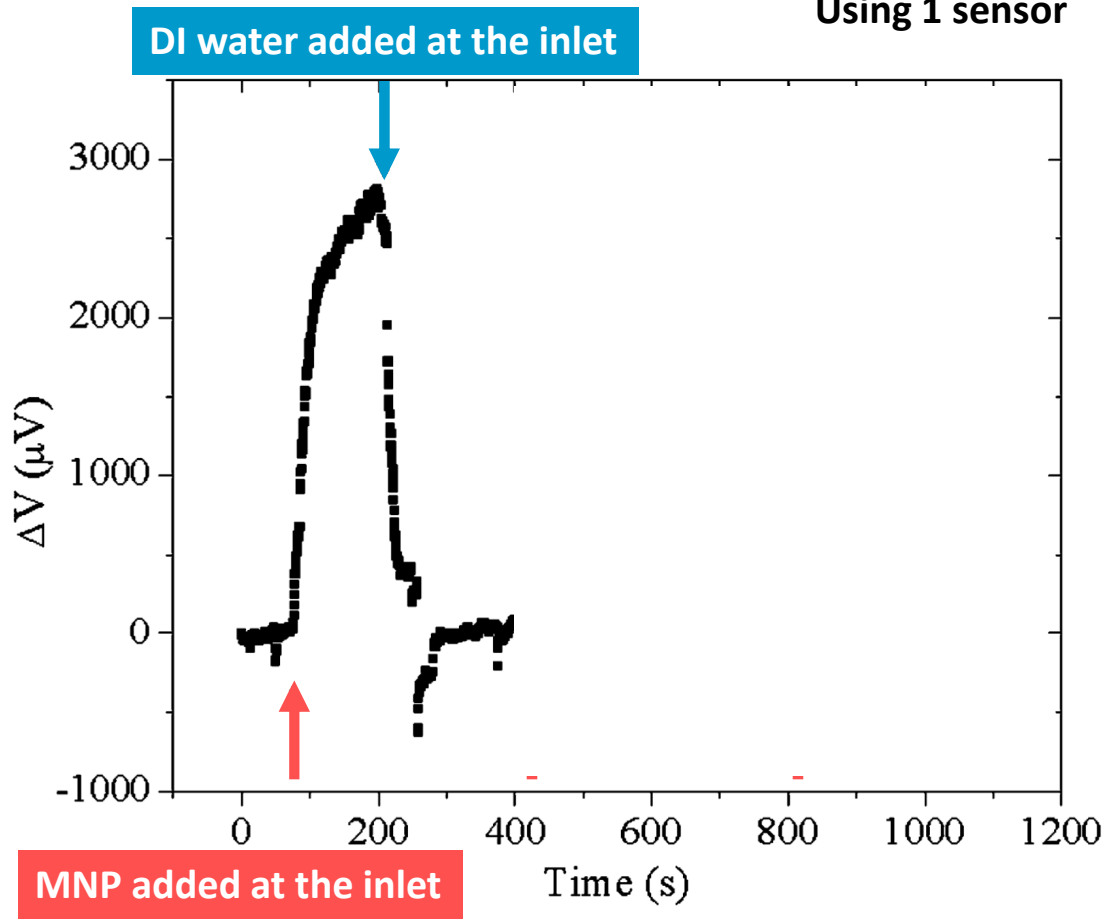
SPIN VALVES FOR VELOCITY MEASUREMENTS

Using 1 sensor

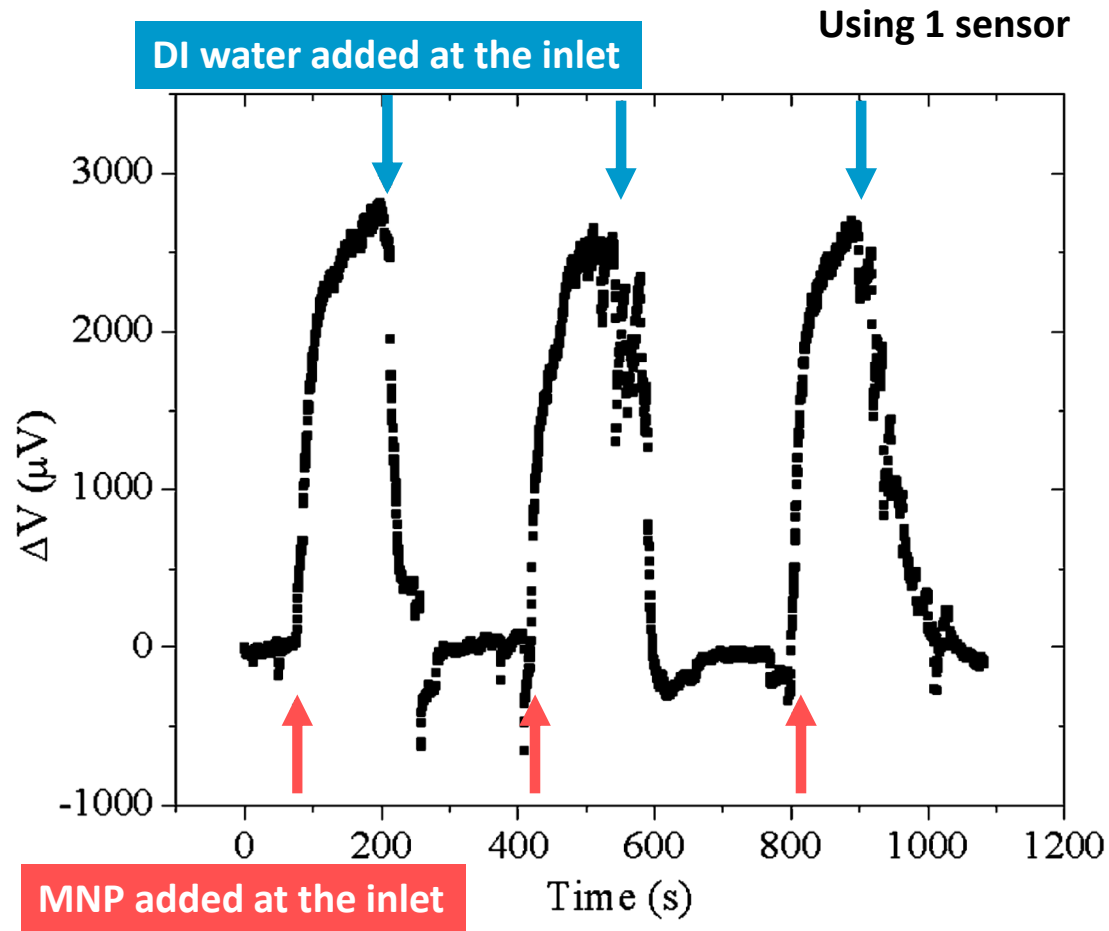


SPIN VALVES FOR VELOCITY MEASUREMENTS

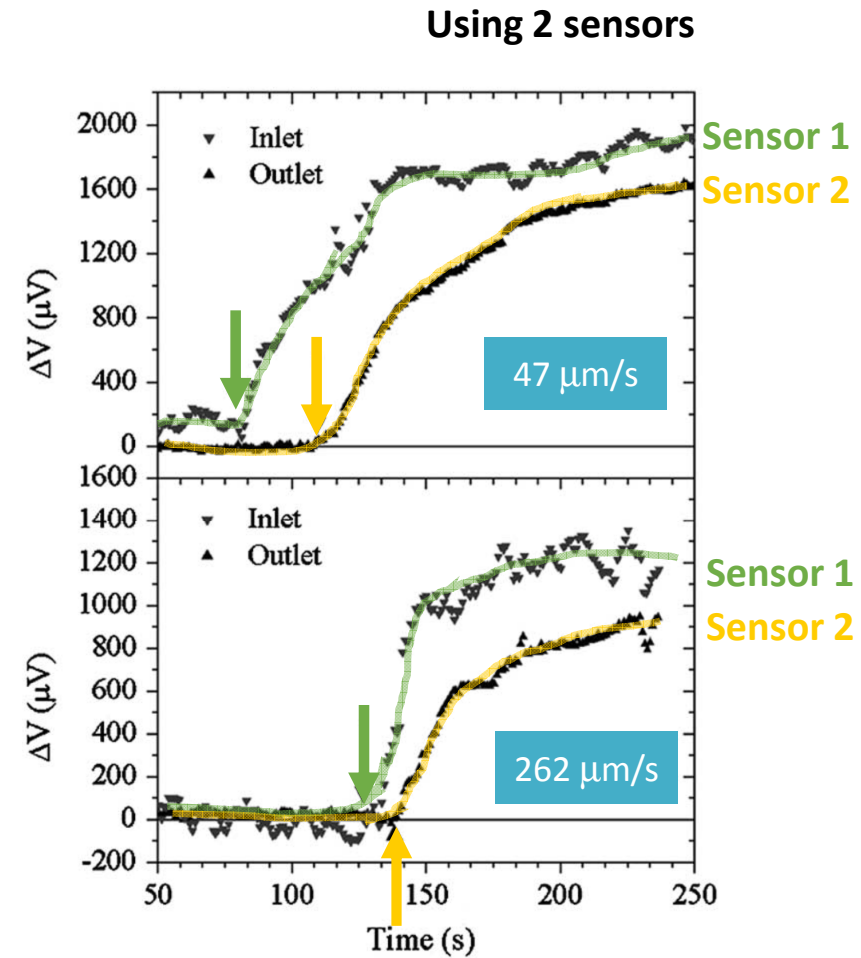
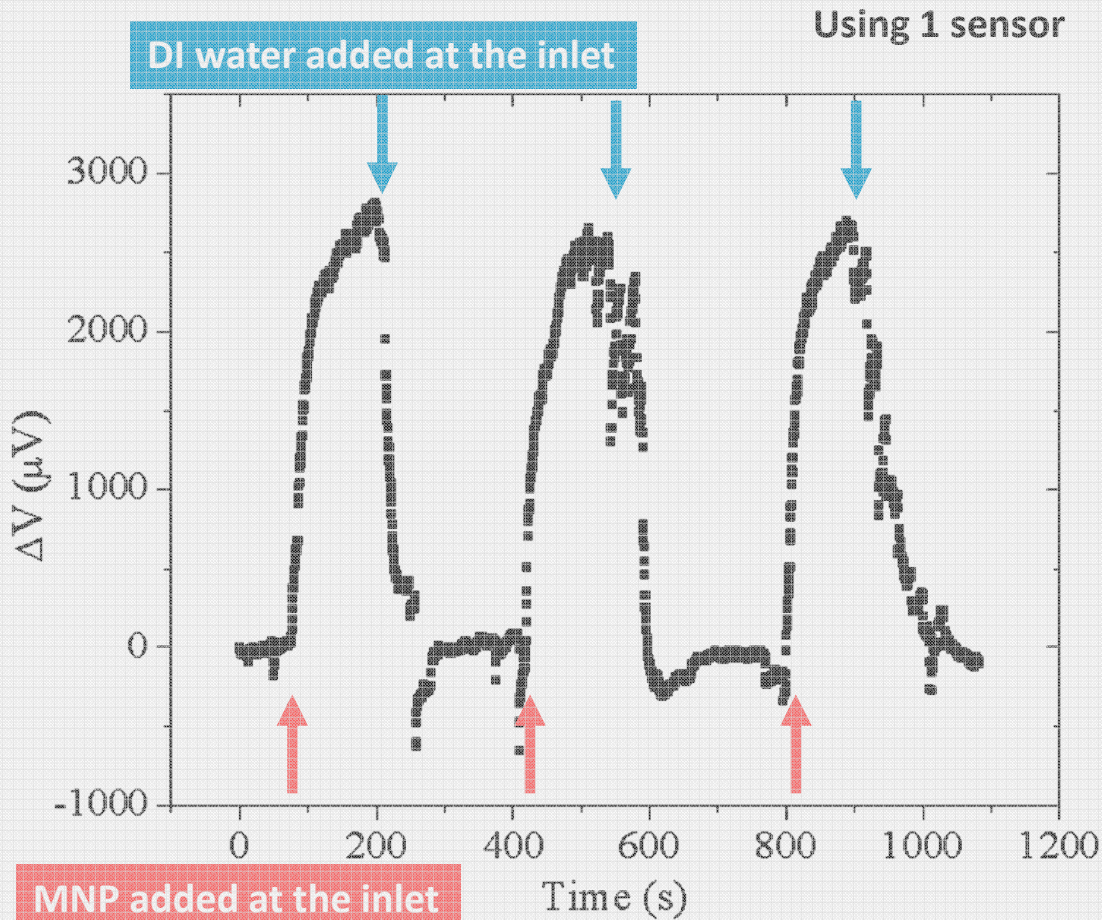
Using 1 sensor



SPIN VALVES FOR VELOCITY MEASUREMENTS



SPIN VALVES FOR VELOCITY MEASUREMENTS



Topical Review

Challenges and trends in magnetic sensor integration with microfluidics for biomedical applications

S Cardoso^{1,2}, D C Leitao^{1,2}, T M Dias^{1,2}, J Valadeiro^{1,2}, M D Silva^{1,2},
A Chicharo^{2,3}, V Silverio¹, J Gaspar³ and P P Freitas^{1,3}

¹ INESC–Microsistemas e Nanotecnologias (INESC-MN) and IN, Rua Alves Redol 9, 1000-029 Lisbon, Portugal

² Instituto Superior Técnico, Universidade de Lisboa, Av. Rovisco Pais, 1049-001 Lisbon, Portugal

³ INL, International Iberian Nanotechnology Laboratory, Av. Mestre Jose Veiga, 4715-330 Braga, Portugal

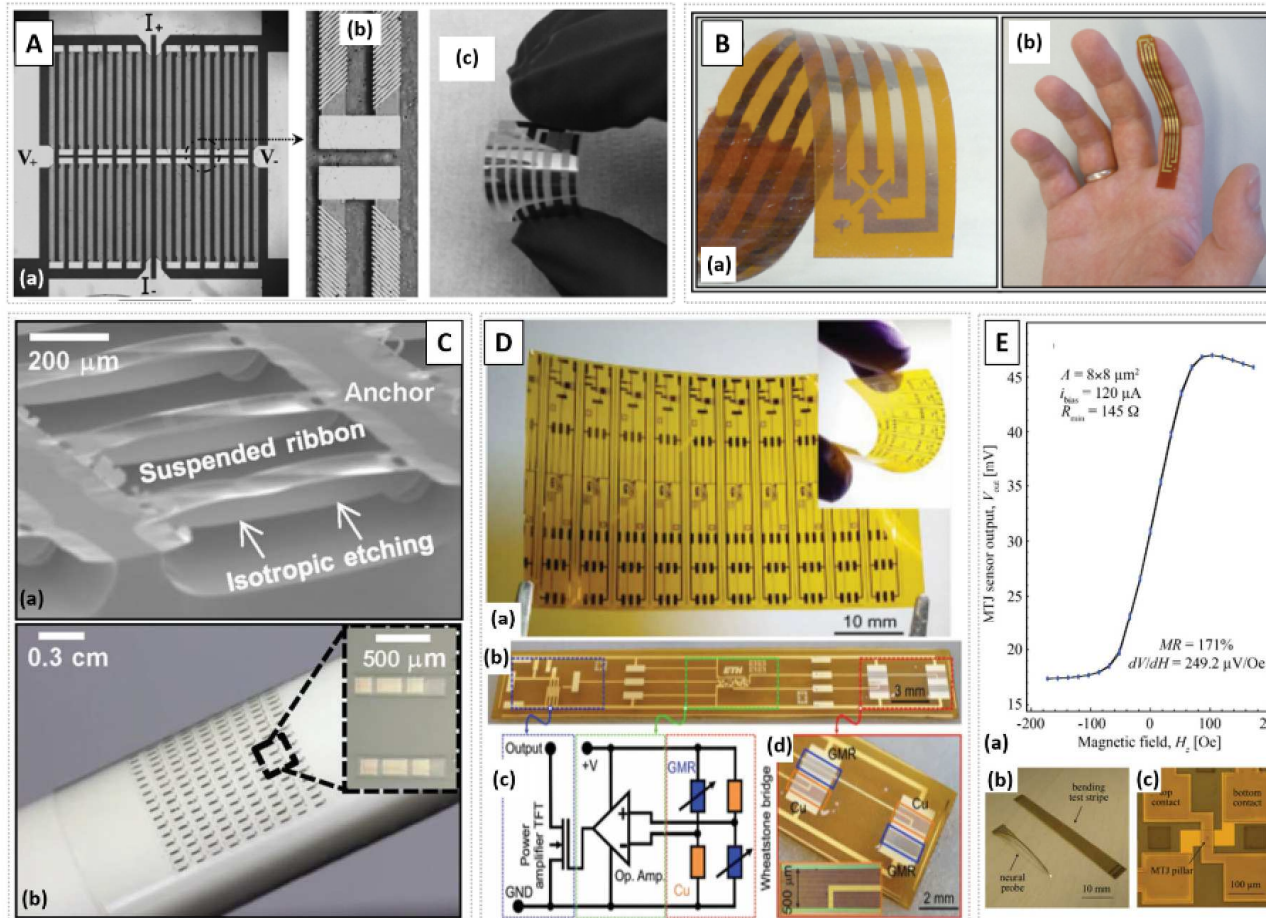


Figure 6. Examples of flexible magnetic sensors. (A) (a) AMR sensors patterned in a Wheatstone bridge configuration on a flexible substrate, (b) zoom over the barbed poles on the NiFe layer, and (c) the AMR sensor on a flexible PET foil. [73] John Wiley & Sons. © 2016 WILEY-VCH Verlag GmbH & Co. KGaA, Weinheim. (B) (a) Flexible Hall sensor which can be (b) conformed to a finger. [76] Copyright Wiley-VCH Verlag GmbH & Co. KGaA. Reproduced with permission. CC BY-NC 4.0. (C) (a) Si undercut etching under the fabricated and annealed MgO structures for transferring to the (b) flexible substrate. [82] John Wiley & Sons. © 2016 WILEY-VCH Verlag GmbH & Co. KGaA, Weinheim. (D) (a) Array of flexible GMR sensors and electronics fabricated on 50 μm polyimide foil and (b)–(d) details over the complete system. [85] Copyright Wiley-VCH Verlag GmbH & Co. KGaA. Reproduced with permission. CC BY-NC 4.0. (E) Representative TMR output of a 8 × 8 μm² MgO-MTJ pillar with stack (Ta (5)/CuN (25)) × 6/Ta (5)/Ru (5)/MnIr (20)/Co₇₀Fe₃₀ (2)/Ru (0.85)/CoFeB (2.6)/MgO (1.0)/CoFeB (2)/Ta (0.21)/NiFe (4)/Ru (0.2)/MnIr (6)/Ru (2)/Ta (5)/Ru (10) (thickness in nm) fabricated and annealed on polyimide substrate; the inset shows an example of released structures and single sensor design. Reproduced with permission from [66]. © Copyright 2017 IEEE.

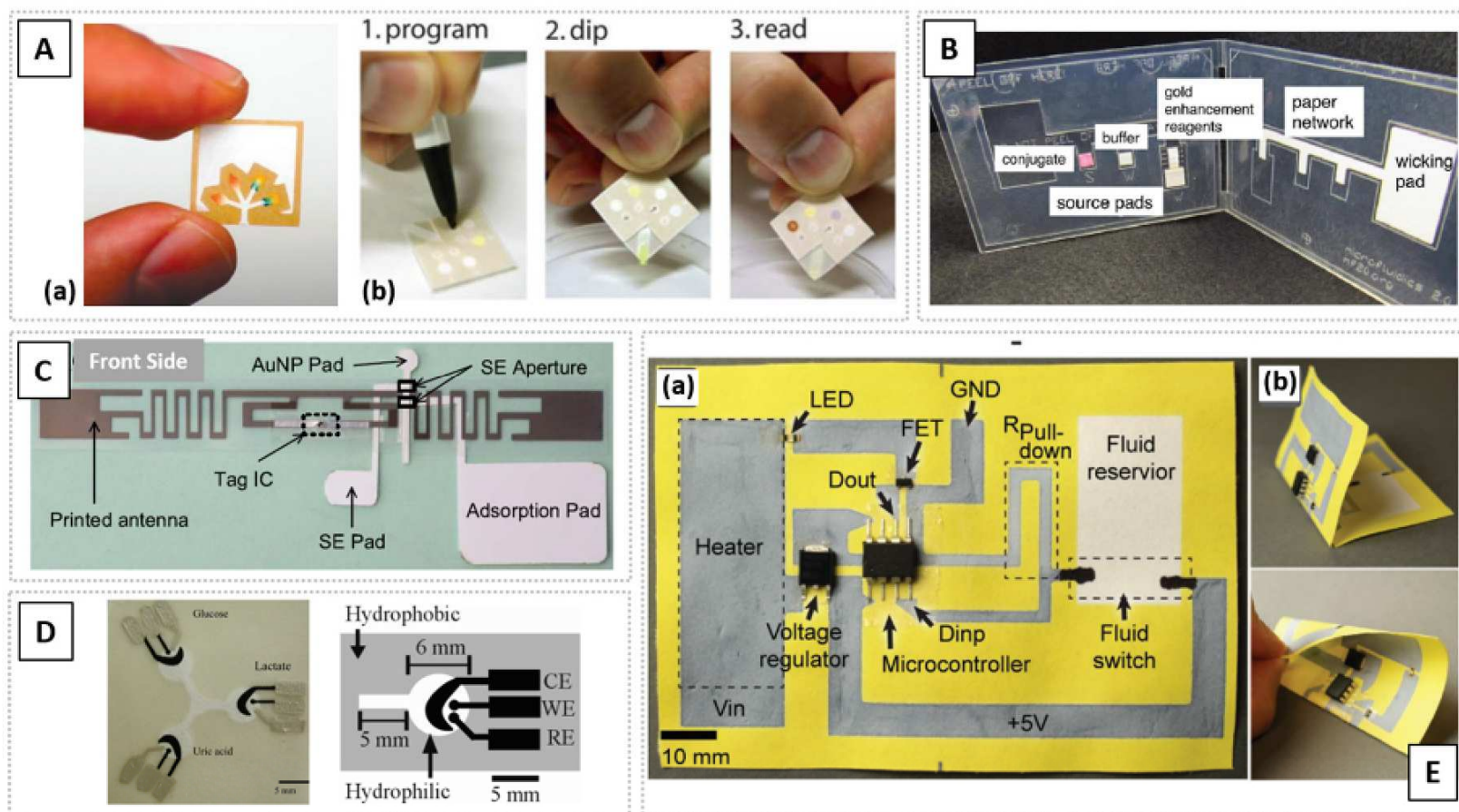


Figure 9. Examples of paper microfluidic applications. (A): (a) Concept of microfluidic paper-based analytical devices (μ PAD). Reprinted with permission from [104]. Copyright 2009 American Chemical Society. (b) Strategy used for a programmable μ PADs for urinalysis. Adapted from [105] with permission of The Royal Society of Chemistry. (B) A 2D paper network card for an amplified immunoassay. Adapted with permission from [109]. Copyright 2012 American Chemical Society. (C) Self-powered RFID biosensor prototype integrating paper-based microfluidics and a self-assembled RF antenna. © 2016 IEEE. Reprinted, with permission, from [117]. (D) Image and schematic design of the electrode paper-based microfluidic device demonstrated by Dungchai *et al.* Adapted with permission from [114]. Copyright 2009 American Chemical Society. (E) Paper-based integrated system incorporating fluidics and electronic components, with wiring connections fabricated in paper and (b) image of the folded paper circuit. [118] John Wiley & Sons. © 2016 WILEY-VCH Verlag GmbH & Co. KGaA, Weinheim.

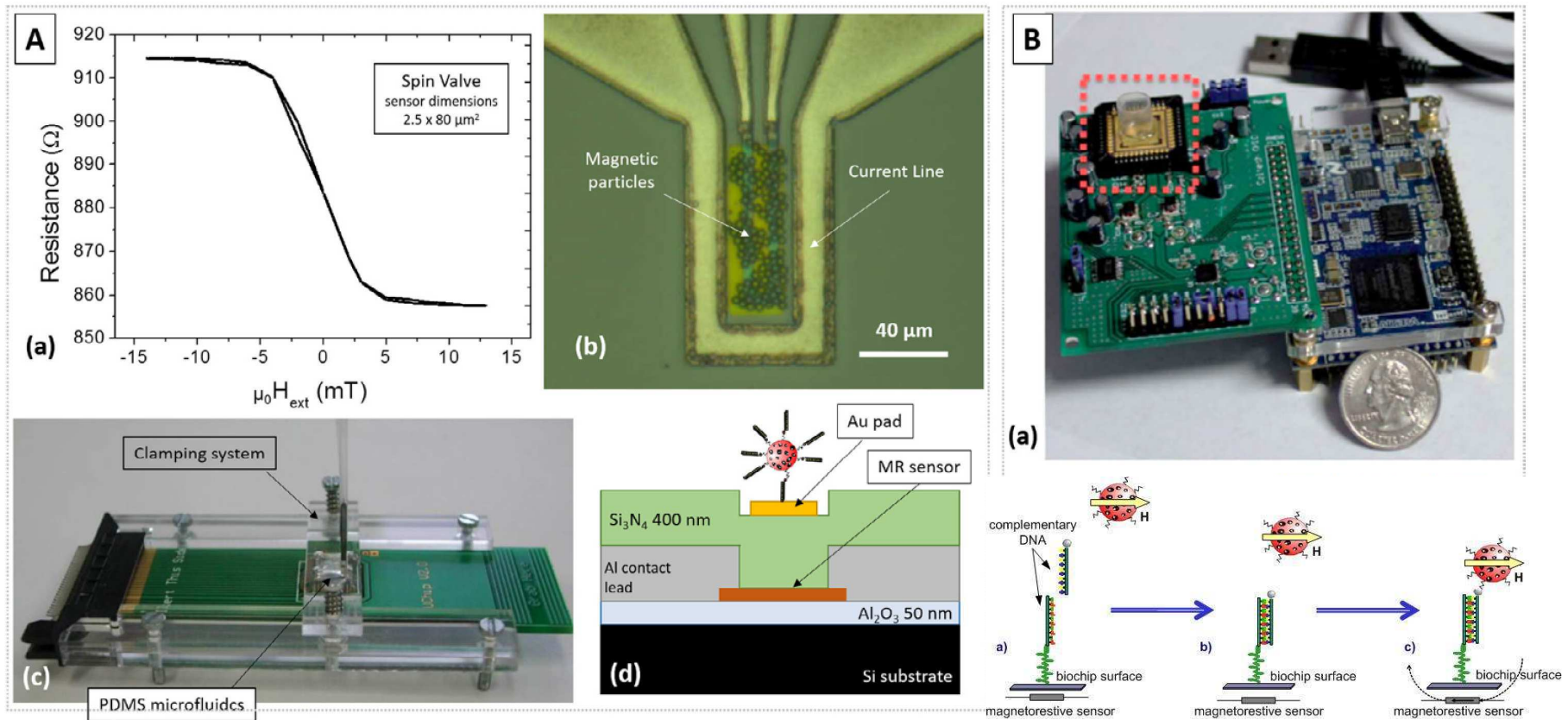
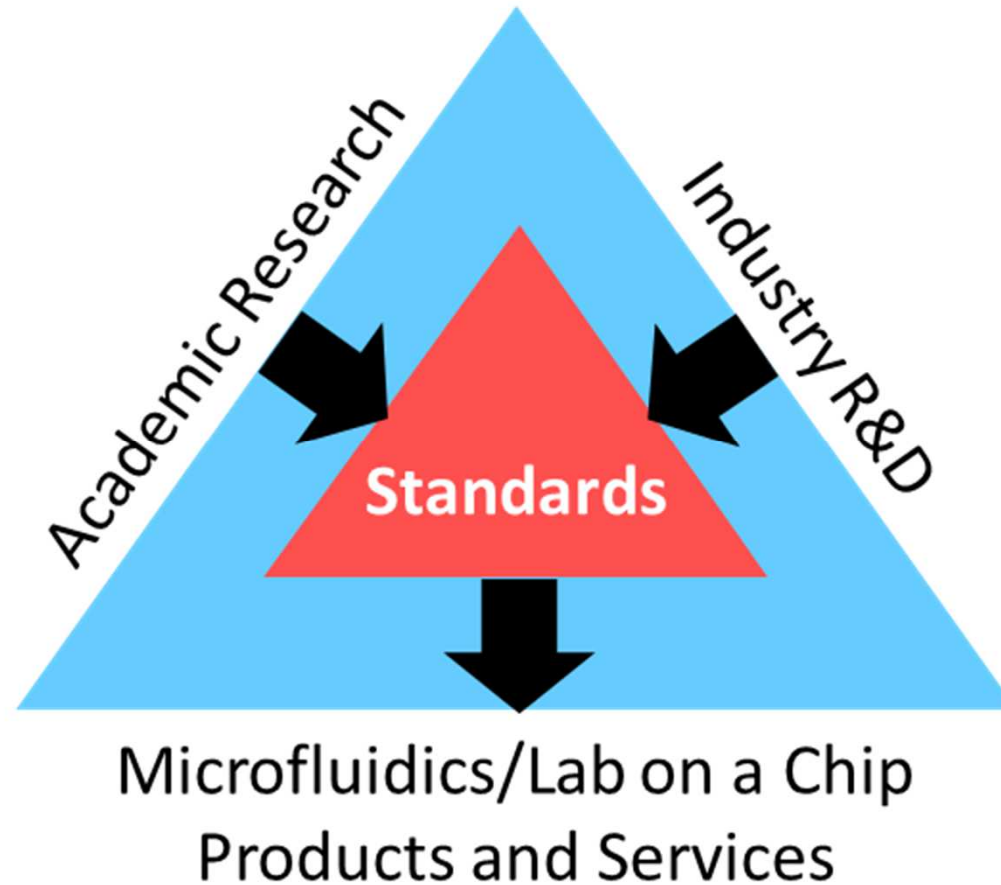


Figure 11. (A) Example of a static detection biochip from INESC-MN. (a) Transfer curve of an SV sensor. (b) Focusing method for magnetic particles using current lines. (c) Clamping device to aid bonding of the PDMS microfluidic channels and (d) cross section of the chip layout. (B) CMOS handheld diagnostic device from Pai *et al* [150]. (a) Device consisting of the plug-in cartridge, circuit board, and USB interface, (b) example of the disposable chip with a polypropylene well and (c) chip layout. [150] Reproduced by permission of The Royal Society of Chemistry. CC BY-NC 3.0.



MICROFLUIDICS STANDARDIZATION ROADMAP



MICROFLUIDICS STANDARDIZATION ROADMAP



INESC MN

Microsystems and
Nanotechnologies

INESC MN'S GREAT TEAM !





INESC MN

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Nanotechnologies

SPINTRONICS AND BIOSENSORS

MEMS AND BIOMEMS

MAGNETIC NANOSTRUCTURES AND NANODEVICES

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VISIT US IN LISBON, PORTUGAL

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THANK YOU FOR YOUR ATTENTION